TOSHIBA CMOS Integrated Circuit Silicon Monolithic

TC32306FTG

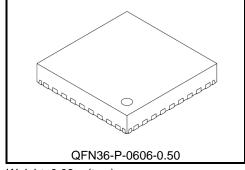
Single-Chip RF Transceiver for Low-Power Systems

1. General Description

The TC32306FTG is a single-chip RF transceiver, which provides many of the functions required for UHF-band transceiver applications. It has the most features transmitting and receiving the signal.

Furthermore, by digital processing, it can reduce significantly the number of external components and allow fine adjustments.

Various type of applications are supported by this chip as configuring various settings such as supply voltage, frequency, modulation and detection.



Weight: 0.08 g (typ.)

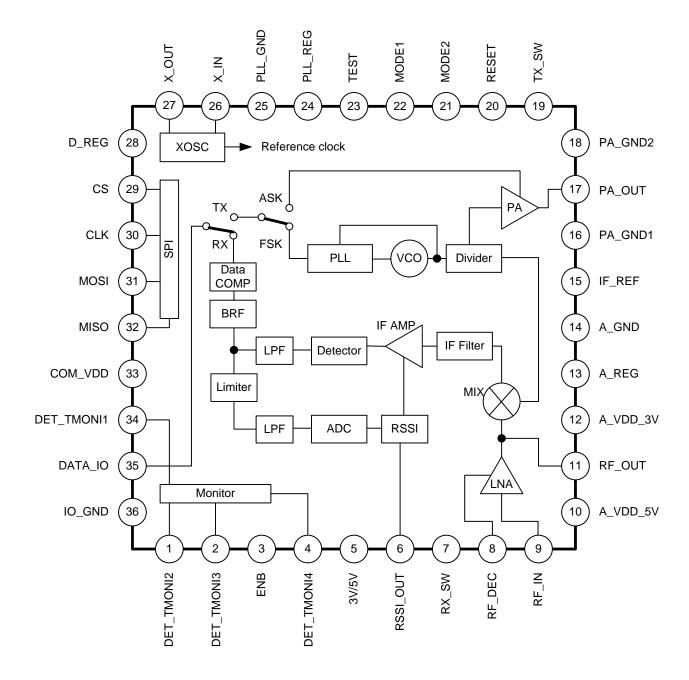
2. Applications

Remote keyless entry (remote door lock / unlock of equipment), automotive equipment applications such as tire pressure monitoring system, and remote controller, etc

3. Features

- Integrates LNA, Mixer, IF Filter, IF AMP, RSSI, Signal Detector, Bit Rate Filter, Data Comparator, PLL, VCO and PA into a single IC.
- Operating voltage range: 2.0 to 3.3 V (For 3V Use), 2.4V to 5.5V (For 5V Use)
- Current consumption: TX 12 mA at +10dBm output level / RX 9.7 mA / Battery Saving 0µA (typ.)
- Use for four RF Band: 315, 434, 868 / 915 MHz
- Supported modulation: ASK / FSK
- Single conversion system
- Two IF Filter bandwidth: wide 320 kHz(typ.) at IF = 230 kHz / middle 270 kHz(typ.) at IF = 280 kHz
- Signal Detections: RSSI detection, Noise detection (Only for FSK), Preamble detection
- Receiver sensitivity: under -116dBm (At IF BW = 320kHz, data rate = 600Hz, frequency deviation = +/-40kHz)
- Transmitter power: +10dBm (typ. at setting maximum output)
- Serial control (4 wire SPI) / EEPROM control
- Data Comparator Quick Charge / AutoOff Control / Antenna Switch Control

4. Block Diagram



Some of the functional blocks, circuits, or constants in the block diagram may be omitted or simplified for explanatory purposes.

Fig 4-1 Block Diagram

5. Pin Description

5.1 Equivalent Circuit and Function

Table 5-1 Pin Description

- All the values (resistance, capacity, etc.) shown in the internal equivalent circuit diagram are typical values.

The equivalent circuit diagrams may be simplified or some parts of them may be omitted for explanatory purpose.

Pin No.	Pin Name	I/O	Description	Internal Equivalent Circuit
1	DET_TMONI2	Digital Output	Monitor 2 Monitoring internal signals (digital), use for system control At no use, open this pin.	COM_VDD COM_VDD DET_TMONI2 1 Control
2	DET_TMONI3	Analog Output	Monitor 3 Monitoring internal signals (Converted to analog / in User Test) At no use, open this pin. Notice: In User Test, Supply at least 3 V to COM_VDD pin to monitor the signal. Lower voltage supply causes an incorrect monitoring.	COM_VDD DET_TMONI3 2
3	ENB	Digital Input	Enable Pin Select to enable (In SPI Mode) Address Setting (In EEPROM Mode) Set a start address to read memory data. Notice: Do not supply higher voltage than the level of COM_VDD. (For example, in the case of too low / no power supply.) That causes overcurrent at this pin, as the ESD protection elements insertion between the pin and the voltage source.	COM_VDD ENB 3
4	DET_TMONI4	Analog Output	Monitor 4 Monitoring internal signals (Converted to analog / in User Test) At no use, open this pin. Notice: In User Test, Supply at least 3 V to COM_VDD pin to monitor the signal. Lower voltage supply causes an incorrect monitoring.	COM_VDD DET_TMONI4 4
5	3V/5V	Digital Input	Supply Voltage Selector Select supply voltage. Connect power supply for 5V use. / Ground for 3V use. Notice: Do not supply higher voltage than the level of COM_VDD. (For example, in the case of too low / no power supply.) That causes overcurrent at this pin, as the ESD protection elements insertion between the pin and the voltage source.	SOM_VDD

Pin No.	Pin Name	I/O	Description	Internal Equivalent Circuit
6	RSSI_OUT	Analog Output		A_VDD_3V A_VDD_3V RSSI_OUT 6 50kΩ
7	RX_SW	Digital Output Digital Input	Antenna Switch Control for RX (In SPI Mode) At no use, open this pin. Address Setting (In EEPROM Mode) Set a start address to read memory data. Notice: Do not supply higher voltage than the level of COM_VDD. (For example, in the case of too low / no power supply.) That causes overcurrent at this pin, as the ESD protection elements insertion between the pin and the voltage source.	A_VDD_5V A_VDD_5V 100Ω $20k \Omega$
8	RF_DEC	-	RF Decoupling Pin Connect a decoupling capacitor. At no use, open this pin.	A_REG A_VDD_3V $1k\Omega$ $6k\Omega$ 9
9	RF_IN	Analog Input	RF Input Pin Do not connect DC voltage except ground to RF_IN pin. At no use, open this pin.	A_REG RF_DEC 8

Pin No.	Pin Name	I/O	Description	Internal Equivalent Circuit
10	A_VDD_5V	-	Analog 5V Supply Supply to mainly analog block For 5V use, supply 5V (typ.) For 3V use, connect A_VDD_3V pin and supply 3V (typ.).	-
11	RF_OUT	Analog Output	RF Output pin RF signal output from LNA block, Open drain output. Connect A_VDD_3V pin via a matching circuit. At no use, open this pin.	RF_OUT 11
12	A_VDD_3V	-	Analog 3V Supply - For 3V use, supply 3V (typ.) For 5V use, voltage regulator output. Connect a bypass capacitor. Do not apply current or voltage on this pin from outside. And do not supply to external circuits except PA_OUT and RF_OUT pin.	-
13	A_REG	Analog Output	Regulator Output for Analog Block Supply to mainly analog block. Connect a bypass capacitor. Do not apply current or voltage on this pin from outside. And do not supply to external circuits.	A_VDD_5V A_VDD_5V A_REG 100pF 150kΩ
14	A_GND	-	Ground (Analog)	-
15	IF_REF	-	IF Reference Connect ground via a capacitor. At no use, open this pin.	$\begin{array}{c} \text{A_VDD_3V} \\ \text{IF_REF} \\ \text{100k}\Omega \\ \end{array}$
16	PA_GND1	-	Power Amplifier Ground 1 At no use of PA, connect ground.	-

Pin No.	Pin Name	I/O	Description		Internal Equivalent Circuit
17	PA_OUT	Analog Output	Power Amplifier Output Stage Open drain output. Connect A_VDD_3V pin via a matching circuit. At no use, open this pin.	PA_OUT	
18	PA_GND2	-	Power Amplifier Ground 2 At no use of PA, connect ground.		-
19	TX_SW	Digital Output Digital Input	Antenna Switch Control for TX (In SPI Mode) At no use, open this pin. Address Setting (In EEPROM Mode) Set a start address to read memory data. Notice: Do not supply higher voltage than the level of COM_VDD. (For example, in the case of too low / no power supply.) That causes overcurrent at this pin, as the ESD protection elements insertion between the pin and the voltage source.	TX_SW (19)—	A_VDD_5V A_VDD_5V $\begin{array}{c} \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\$
20	RESET	Digital Input	Reset Initialize TC32306FTG.	RESET 20	
21	MODE2	Digital Input	Mode Control Select SPI Mode, SPI User Test Mode, EEPROM Mode, EEPROM User Test Mode.	MODE2	
22	MODE1	Digital Input	Mode Control Select SPI Mode, SPI User Test Mode, EEPROM Mode, EEPROM User Test Mode.	MODE1 (22)—	40kΩ
23	TEST	Digital Input	TEST Only use for Toshiba test. Connect ground.	TEST 23—	40kΩ

Pin No.	Pin Name	I/O	Description	Internal Equivalent Circuit
24	PLL_REG	Analog Output	Regulator Output for PLL Supply to mainly PLL block. Connect a bypass capacitor. Do not supply voltage, and do not supply to an external circuit.	COM_VDD COM_VDD Vref O 150kΩ
25	PLL_GND	1	Ground(Digital)	-
26	X_IN	Analog Input	Reference Clock Input Connect crystal oscillator or external signal generator. Do not apply a DC bias voltage.	PLL_REG X_IN
27	X_OUT	Analog Output	Reference Clock Output Open this pin except a crystal oscillator use. Do not apply current or voltage on this pin from outside. And do not supply the clock signal to external circuits.	26 300kΩ PLL_REG X_OUT
28	D_REG	Analog Output	Regulator Output for Digital Block Supply to mainly digital block. Connect a bypass capacitor. Do not apply current or voltage on this pin from outside. And do not supply to external circuits.	COM_VDD COM_VDD Vref O 150kΩ

Pin No.	Pin Name	I/O	Description	Internal Equivalent Circuit
29	CS	Digital Input Digital Output	Chip Select Input In SPI Mode / SPI User Test Mode / EEPROM User Test Mode. Notice: Do not supply higher voltage than the level of COM_VDD. (For example, in the case of too low / no power supply.) That causes overcurrent at this pin, as the ESD protection elements insertion between the pin and the voltage source. Chip Select Output In EEPROM Mode.	COM_VDD COM_VDD COntrol
30	CLK	Digital Input	SPI Clock Input In SPI Mode / SPI User Test Mode / EEPROM User Test Mode. Notice: Do not supply higher voltage than the level of COM_VDD. (For example, in the case of too low / no power supply.) That causes overcurrent at this pin, as the ESD protection elements insertion between the pin and the voltage source. SPI Clock Output	COM_VDD COM_VDD COM_VDD
31	MOSI	Digital Input Digital Output	In EEPROM Mode. Serial Data Input In SPI Mode / SPI User Test Mode / EEPROM User Test Mode. Notice: Do not supply higher voltage than the level of COM_VDD. (For example, in the case of too low / no power supply.) That causes overcurrent at this pin, as the ESD protection elements insertion between the pin and the voltage source. Serial Data Output In EEPROM Mode.	Control COM_VDD

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Pin No.	Pin Name	I/O	Description	Internal Equivalent Circuit
		Digital Output	Serial Data Output In SPI Mode / SPI User Test Mode / EEPROM User Test Mode.	Control
32	MISO	Digital Input	Serial Data Input In EEPROM Mode. Notice: Do not supply higher voltage than the level of COM_VDD. (For example, in the case of too low / no power supply.) That causes overcurrent at this pin, as the ESD protection elements insertion between the pin and the voltage source.	MISO COM_VDD COntrol
33	COM_VDD	-	Common Voltage Supply Use for 3V and 5V. Supply to mainly control block.	-
34	DET_TMONI1	Digital Output	Monitor 1 Monitoring internal signals (Digital), use for system control. At no use, open this pin.	COM_VDD COM_VDD DET_TMONI1 34 Control
35	DATA_IO	Digital Output Digital Input	Data Output Demodulated signal output at RF-Receiving. Behavior of this pin is different for each state of TC32306FTG reset. See Table 5-2. Notice: Output resistance of this pin is $10k\Omega$ when the output drive setting is "Low". Select proper resistance value of pull-up or pull down resistor to get enough output level of the pin, when the output drive setting is "Low". Or select that the output drive setting is "High", depending on the resistance value of the resister. About output drive settings, see section 6.10.5. Data Input Signal input for modulation at RF-Transmitting. Behavior of this pin is different for each state of TC32306FTG reset. See Table 5-2. Notice: Do not supply higher voltage than the level of COM_VDD. (For example, in the case of too low / no power supply.) That causes overcurrent at this pin, as the ESD protection elements insertion between the pin and the voltage source.	Low Drive Control COM_VDD High Drive Control
36	IO_GND	_	Ground(I/O Block)	_
50	10_0110		J. January Blooky	<u>-</u>

5.2 Pin Behaviors at Reset and Register Initialized

Several pin behaviors of TC32306FTG depend on setting of Reset, register's initial value, or SPI Mode / EEPROM Mode (including User Test). See Table 5-2.

Table 5-2 Pin Behaviors at Reset and Register Initialized

Pin	SPI Mode (TC32306FTG is slave.) (Including SPI User Test Mode)		EEPROM Mode (TC32306FTG is master.)		EEPROM User Test Mode (TC32306FTG is slave.)	
	RESET = "L"	Register's Initial (Battery Saving)	RESET = "L"	Battery Saving	RESET = "L"	Register's Initial (Battery Saving)
MODE2	IN	IN	IN	IN	IN	IN
MODE1	IN	IN	IN	IN	IN	IN
CS	IN	IN	High Output	High Output	IN	IN
CLK	IN	IN	Low Output	Low Output	IN	IN
MOSI	IN	IN	Low Output	Low Output	IN	IN
MISO	Z	Z	Z	Z	Z	Z
ENB	IN	IN	IN	IN	IN	IN
TX_SW	Pull Down	Pull Down	IN	IN	IN	IN
RX_SW	Pull Down	Pull Down	IN	IN	IN	IN
DATA_IO	Z	Low Output	Z	Low Output	Z	Low Output
DET_TMONI1,2	Low Output	Low Output	Low Output	Low Output	Low Output	Low Output
DET_TMONI3,4	Z	Z	Z	Z	Z	Z

Z: High Impedance

Notice: In SPI Mode, TC32306FTG accepts the input of SPI settings at RESET = "L", but will not act.

In Battery Saving Status, DATA_IO pin behavior changes to the value of register:h'0A[D5]RX_TX. Initial value of register:h'0A[D5]RX_TX is "0".

Table 5-3 DATA_IO Pin Behavior in Battery Saving

Pin	h'0A[D5]RX_TX = "0" (RX: Initial)	h'0A[D5]RX_TX = "1" (TX)
DATA_IO	Low Output	Z

Z: High Impedance

In Battery Saving Status, MISO pin changes its behavior at SPI Read when TC32306FTG is slave.

Table 5-4 MISO Pin Behavior in Battery Saving (TC32306FTG is slave.)

Pin	At SPI Read	Except SPI Read
MISO	OUT	Z

Z: High Impedance

6. Functional Description

6.1 Voltage Supply Settings

The voltage supply of TC32306FTG is selectable either 3V or 5V. The supply voltage is selected by setting of 3V/5V pin, and it decides pin connections. At 5V use, connect 3V/5V pin to a voltage supply, then the internal voltage regulator (A_REG30; for analog 3V) makes 3V (typ.) for internal circuit and outputs same to A_VDD_3V pin for the matching of LNA and PA.

Pin Name	3V Use	5V Use
3V/5V (Behavior of A_REG30 Regulator)	GND (Disable)	5V Supply Input (Enable)
A_VDD_3V	3V Supply Input	Output of A_REG30 Regulator (Do not supply to external circuits.)
A_VDD_5V	3V Supply Input	5V Supply Input
COM_VDD	3V Supply Input	5V Supply Input

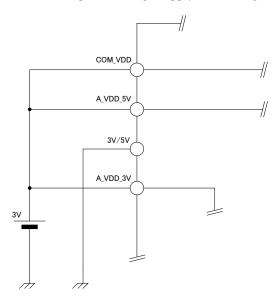
Table 6-1 Voltage Supply Pins Connection

6.1.1 3V Use

At 3V use, connect 3V/5V pin to ground. Connect COM_VDD pin, A_VDD_3V pin and A_VDD_5V pin to a stable 3V supply.

Notice:

- Must not operate A_REG30 regulator for 5V use.
- Must not connect COM_VDD pin to voltage supply out of range of $V_{\text{DD(3V)}}$ shown as Table 8-1.



(This figure is conceptual. Select bypass capacitors in application circuits.)

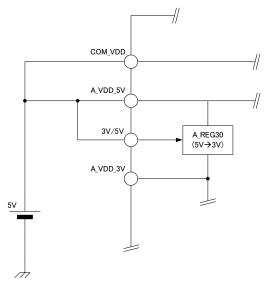
Fig 6-1 Example of Voltage Supply Connection at 3V Use

6.1.2 5V Use

At 5V use, connect 3V/5V pin to the 5V supply. Connect A_VDD_5V pin and COM_VDD pin to a stable 5V supply.

Notice:

- Must not connect A_VDD_3V pin to outside voltage supply.
- Must not connect COM_VDD pin to voltage supply out of range of VDD(5V) shown as Table 8-1.
- Must use a voltage supply from A_VDD_3V pin (output of A_REG30 regulator), for the matching circuit of LNA and PA.



(This figure is conceptual. Select bypass capacitors in application circuits.)

Fig 6-2 Example of Voltage Supply Connection at 5V Use

6.1.3 Supply / Ground Connections

In TC32306FTG supply / ground connections are separated for each functional block. At 5V use, some of analog functional blocks are connected internal 3V regulator (A_REG30 regulator). At 3V use, some of analog functional blocks are connected directly 3V supply, by connecting A_VDD_3V / A_VDD_5V pin.

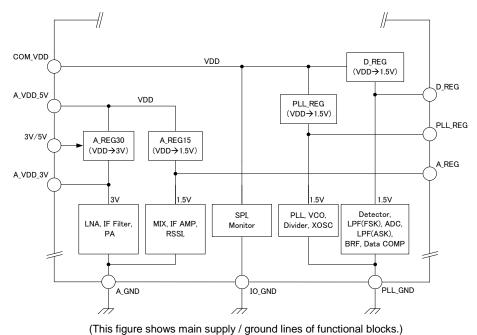


Fig 6-3 Conceptual Supply / Ground Connection to Functional Blocks

6.2 Control Mode Settings

TC32306FTG has two control modes, SPI (Serial Peripheral Interface) Mode and EEPROM Mode. The control mode settings are selected by MODE2 pin. User Test Mode in each Control Mode is selected by MODE1 pin.

Table 6-2 Mode of Control

MODE2 Pin	MODE1 Pin	Control Mode Setting
L	L	SPI Mode
L	Н	SPI User Test Mode
Н	L	EEPROM Mode
Н	Н	EEPROM User Test Mode

SPI Mode and EEPROM Mode have a difference about an external connection, pin functions and control signal flows. Do not change the Mode settings in the market products.

Table 6-3 Role of Pin and Control Setting

Control Setting	CS Pin	CLK Pin	MOSI Pin	MISO Pin	ENB Pin	TX_SW Pin	RX_SW Pin
SPI Mode	"Input"		"Output"	"Input"	"Out	put"	
SPI User Test Mode	This IC is slave, controlled by MCU.		This IC is slave, controlled by MCU.	For this IC status control.	For antenn con		
EEPROM Mode	"Output" This IC is master, controls EEPROM.		"Input" This IC is master, reads EEPROM data.	"Input"			
EEPROM User Test Mode	"Input" This IC is slave, controlled by MCU.		"Output" This IC is slave, controlled by MCU.	For EEPROM configuration settings		ettings	

6.2.1 SPI Mode Setting and Connection

MCU and TC32306FTG are connected by SPI lines and MCU controls this IC.

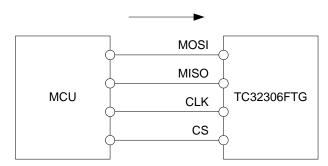


Fig 6-4 Conceptual Connection MCU and TC32306FTG

6.2.2 EEPROM Mode Setting and Connection

EEPROM and MCU, connect via TC32306FTG. This IC is controlled by the register data of EEPROM. Select up to 8 configuration that are made as registers from "h'0A" to "h'1C", depending on the size of EEPROM. In this mode, use of pins and external connections are different from those of SPI Mode. For example, $TX_SW / RX_SW / ENB$ pin are used to select configuration of EEPROM.

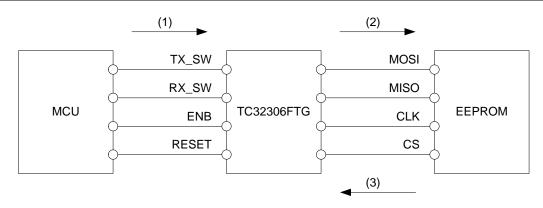


Fig 6-5 Conceptual Connection MCU, EEPROM and TC32306FTG

- In advance, write registers' values to each configuration data area of EEPROM.
- MCU commands this IC for selecting configuration data area of EEPROM. (1)
- This IC read a configuration data from EEPROM by SPI lines at the rising edge of RESET pin signal. (2)
- This IC is operated depending on EEPROM data. (3)

6.3 Universal Functions and Settings

6.3.1 Reset Status

The internal condition (such as the register value) of TC32306FTG is initialized in this Status. For this IC Reset, input "L" signal to RESET pin surely during stable voltage supply. Also releasing Reset of this IC should be operated during stable voltage supply.

RESET Pin	IC Status
L	Initialize registers and I/O behaviors. Because I/O will be initialized, TC32306FTG does not accept all the settings except some settings. * About I/O behaviors at Reset status, see Table 5-2.
Н	Battery Saving / Standby / Run by this IC settings.

Table 6-4 RESET Pin Control

Notice:

- Must be reset after voltage supply.
- The value of registers is initialized immediately after reset is released.
- See Table 5-2 of I/O behavior at the register initialized.
- In SPI Mode, TC32306FTG stays Battery Saving from Reset to register setting input, which moves to Run after reset will be released.
- In EEPROM Mode, the internal oscillator circuit for reading EEPROM will start after reset is released.
- Controlling to RESET pin in starting operation of this IC, keep reset status till supply voltage is over 90% of system voltage stably. Wait at least 1 microsecond after reaching that voltage level. Then reset can be released. In the transient starting operation, reset release may cause to be unexpected operation of this IC.

About RESET pin control in starting operation, see Fig 6-6.

^{*} In EEPROM Mode, ENB pin / TX_SW pin / RX_SW pin are available.

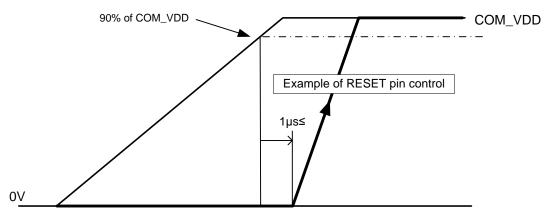


Fig 6-6 Example of RESET Pin Control in Starting Operation

- Software Reset

Software Reset will start after write "b'01010101" to register: h'09[D7:D0]RESET7..0. TC32306FTG will be reset as soon as the writing of Software Reset. Then the reset is released by next rising edge of CLK Signal or CS Signal, whichever is earlier. This IC will stay Battery Saving Status till the next Run / Standby command writing.

Table 6-5 Software Reset Command

Software Reset Command
h'09[D7:D0]RESET70 = b'01010101

Notice:

- Not available in EEPROM Mode (Except EEPROM User Test Mode)
- At Software Reset, only the register will be reset.
- TC32306FTG will output "b'000000000" to read the register: h'09[D7:D0]RESET7..0.

6.3.2 Status Control

After reset is released, TC32306FTG has three status, Battery Saving / Standby / Run, then those status are controlled by two registers "h'oA[D7] / h'oA[D6]" and ENB pin. In EEPROM Mode, ENB pin is used for configuration setting.

Table 6-6 IC Status in SPI Mode

MODE2 Pin	ENB Pin	h'0A[D7]ENB	h'0A[D6]ACT	Status	Description
L	L	X	Х	Battery	The lowest current consumption status. TC32306FTG only can accept control data (register setting) and control settings
L	Н	0	Х	Saving	and they can be changed. The transition from this status to Run will spend longer time than Standby
L	Н	1	0	Standby	This IC can move from this status to Run quickly. This IC can accept control data and operate XOSC and regulators, and consume more current than Battery Saving.
L	Н	1	1	Run	This IC can operate TX and RX. This IC current consumption and status transition time depend on the behaviors.

X: Don't care

In SPI Mode, MODE 1 pin is unrelated to the status control of TC32306FTG. Moving to Battery Saving by AutoOff function, registers "h'0A[D7] ENB, h'0A[D6] ACT" keep the value "1".

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Table 6-7 IC Status in EEPROM Mode

MODE2 Pin	h'0A[D7]ENB	h'0A[D6]ACT	Status	Description
н	0	×	Battery Saving	The lowest current consumption status. TC32306FTG only can accept control settings and they can be changed. The transition from this status to Run will spend longer time than Standby
Н	1	0	Standby	This IC can move from this status to Run quickly. This IC can accept control data and operate XOSC and regulators, and consume more current than Battery Saving.
Н	1	1	Run	This IC can operate TX and RX. This IC current consumption and status transition time depend on the behaviors.

X: Don't care

In EEPROM Mode, MODE1 pin "H" leads EEPROM User Test Mode. In EEPROM User Test Mode, this IC will change to be slave. In EEPROM Mode and EEPROM User Test Mode, ENB pin sets EEPROM address of configuration data and is unrelated to the status control of this IC. Moving to Battery Saving by AutoOff function, registers "h'0A[D7] ENB, h'0A[D6] ACT" keep the value "1".

6.3.3 Output Drive Settings

Select output drive setting at DATA_IO pin / MISO pin / DET_TMONI1 pin / DET_TMONI2 pin by setting registers "h'0D[D3]DATA_IO_D, h'0D[D2]MISO_D, h'0D[D1]TMONI_D". The settings become valid when reset is released (RESET = "H").

Table 6-8 Output Drive Settings

h'0D[D3]DATA_IO_D	DATA_IO pin drive setting		
h'0D[D2]MISO_D	MISO pin drive setting		
h'0D[D1]TMONI_D	DET_TMONI1, DET_TMONI2 pin drive setting		
0	Low drive setting		
1	High drive setting		

6.3.4 Antenna Switch Control

It is a function to control external antenna switch. Set registers "h'0A[D3]TX_SW, h'0A[D2]RX_SW", and TC32306FTG outputs control signals from TX_SW / RX_SW pin. The controls become valid at Run and Standby Status. These pins cannot be available in EEPROM Mode and EEPROM User Test Mode as using for input pins.

Table 6-9 Antenna Switch Control Settings

MODE2 Pin	Ctatus	h'0A[D3]TX_SW	TX_SW Pin
WODEZ PIII	Status	h'0A[D2]RX_SW	RX_SW Pin
L	Buttery Saving	X	L
L	Run / Standby	0	L
L	Run / Standby	1	Н
Н	Х	X	Input pin

X: Don't care

Notice: These pins condition "L" is pulled down through a resistor. External circuit cannot be driven in these pins condition.



6.3.5 Monitoring Control

Set registers "h'14[D6:D4], h'14[D2:D0]" and TC32306FTG outputs monitoring signals from DET_TMONI1 pin / DET_TMONI2 pin. The controls become valid at Run or Standby Status.

Table 6-10 Monitoring Signals

Olahua	h'14[D6] MONI1_SEL2	h'14[D5] MONI1_SEL1	h'14[D4] MONI1_SEL0	DET_TMONI1 Pin Output Signal
Status	h'14[D2] MONI2_SEL2	h'14[D1] MONI2_SEL1	h'14[D0] MONI2_SEL0	DET_TMON2 Pin Output Signal
Battery Saving	X	X	X	Low level output
Run / Standby	0	0	0	Low level output
Run / Standby	0	0	1	DET_out
Run / Standby	0	1	0	Preamble_DET_out
Run / Standby	0	1	1	RSSI_DET_out
Run / Standby	1	0	0	NDET_out
Run / Standby	1	0	1	Status_MONI
Run / Standby	1	1	0	Un_DET_out
Run / Standby	1	1	1	PLL_LD

X: Don't care

(1) DET_out Signal

TC32306FTG outputs the result of overall "Detection" judgment depending on RSSI detection, Noise detection and/or Preamble detection.

L: NOT determine "Signal Detection"

H: Determine "Signal Detection"

Set register:h'10[D2]DET_out_cnt_en="1", TC32306FTG holds DET_out output level "H" after first "Signal Detection".

Table 6-11 DET_out Signal Settings

h'10[D2] DET_out_cnt_en	DET_out Signal
0	Sequential updating
1	Hold output level "H" after first "Signal Detection"

Notice: To release DET_out signal output holding, move to Battery Saving / Standby Status.

(2) Preamble_DET_out Signal

TC32306FTG outputs the result of "Signal Detection" by Preamble Detector.

L: NOT determine "Signal Detection"

H: Determine "Signal Detection"

(3) RSSI_DET_out Signal

 ${\it TC32306FTG}$ outputs the result of "Singnal Detection" by RSSI Detector.

L: NOT determine "Signal Detection"

H: Determine "Signal Detection"

(4) NDET_out Signal

TC32306FTG outputs the result of "Signal Detection" by Noise Detector.

L: NOT determine "Signal Detection"

H: Determine "Signal Detection"

(5) Status_MONI Signal

TC32306FTG outputs its status.

L: Battery Saving

H: Standby / Run

(6) Un_DET_out Signal

TC32306FTG outputs the result of overall "No Signal Detection" judgment depending on RSSI detection , Noise detection and/or Preamble detection.

L: NOT determine "No Signal Detection"

H: Determine "No Signal Detection"

(7) PLL_LD Signal

TC32306FTG outputs the result of PLL lock detection.

L: No PLL lock detection

H: PLL lock detection.

Table 6-12 Logic of DET_out, Un_DET_out Signal

Detection			
RSSI Detection Signal	Noise Detection Signal	Preamble Detection Signal	DET_out Signal
*	*	Н	Н
*	*	L	L
*	Н	OFF	Н
Н	L/OFF	OFF	Н
L/OFF	L/OFF	OFF	L

No Detection			
RSSI Detection Signal	Noise Detection Signal	Preamble Detection Signal	Un_DET_out Signal
*	*	Н	Н
Н	Н	L/OFF	Н
L	Н	L/OFF	L
OFF	Н	L/OFF	Н
*	L	L/OFF	L
Н	OFF	L/OFF	Н
L	OFF	L/OFF	L
OFF	OFF	L/OFF	L

OFF: Stopping signal detection

H: "Signal Detection" is determined.

L: TC32306FTG cannot determine "Signal Detection".

^{*:} Don't Care

H: "No Signal Detection" is determined.

L: TC32306FTG cannot determine "No Signal Detection".

OFF: Stopping signal detection

^{*:} Don't Care

6.4 Local Oscillator

6.4.1 Local Oscillation Abstracts

Table 6-13 Local Oscillation Abstracts

Item	Function
Reference Clock Frequency	30.32MHz (Fixed)
PLL	Fractional - N PLL
VCO Frequency	1732 - 1896MHz
Divider	1/6, 1/4, 1/2 (Setting three stages)
Local Frequency	315, 434, 868 / 915 MHz

6.4.2 Reference Clock

Prepare 30.32 MHz reference clock for TC32306FTG. To use crystal oscillator, connect it between X_IN pin and X_OUT pin with load capacitors. This IC is designed and considered to connect a crystal oscillator with the load capacitance of 6pF.

To use an external signal generator, for example TCXO, connect it to X_IN Pin via a coupling capacitor. Also Open X_OUT Pin and keep input signal level range from 0.5 V to 1.5 V (Peak to peak). Don't supply reference clock signal to external circuit from X_OUT pin.

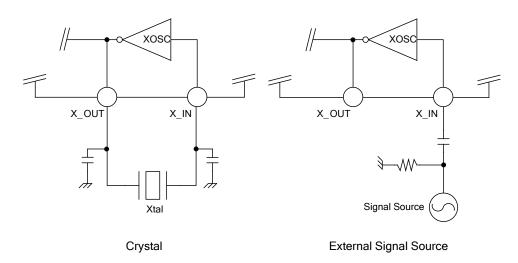


Fig 6-7 Case of Reference Clock Circuit

6.4.3 Local Oscillation

Local oscillator block consists of the fractional-N PLL, VCO and frequency divider. Local frequency is the output of frequency divider. Select the division ratio for expected frequency band. Set register:h'0A[D1:D0] and select the division ratio.

Table 6-14 RF Frequency & Division Ratio

h'0A[D1] BAND1	h'0A[D0] BAND0	RF Frequency Band	Division Ratio
0	0	315MHz	6
0	1	434MHz	4
1	Х	868 / 915MHz	2

X: Don't care

Set the integer counter and fractional counter of registers "h'0B[D7:D0], h'0C[D7:D0]" to set Local frequency. When PLL is locked to the expected frequency, PLL_LD signal turns to be "H". To output

PLL_LD signal from DET_TMONI1 pin and/or DET_TMONI2 pin, set registers"h'14[D6:D4], [D2:D0]".

(1) Local Oscillation Setting for RX

Set Local Oscillator frequency at "Lower Local".

"Receiving Local Frequency" = "RF Recieving Frequency"-"IF Frequency" = "VCO Frequency" / "Division Ratio"

Example 1

RF Frequency: 314.94MHz, IF Frequency: 280kHz, Division Ratio: 6 (Select 315MHz band)

"Receiving Local Frequency" = 314.94MHz - 0.28MHz = 1887.96MHz / 6

Example 2

RF Frequency: 314.94MHz, IF Frequency: 230kHz, Division Ratio: 6 (Select 315MHz band)

"Receiving Local Frequency" = 314.94MHz - 0.23MHz = 1888.26MHz / 6

(2) Local Oscillation Setting for TX

Set Local Oscillator frequency equal to RF transmitting frequency.

"Transmitting Local Frequency" = "RF Transmitting Frequency" = "VCO Frequency" / "Division Ratio"

Example

RF Frequency: 314.94MHz, Division Ratio: 6 (Select 315MHz band) "Transmitting Local Frequency" = 314.94MHz =1889.64MHz / 6

6.5 RF Receiver

For RF-Receiving, set register: h'0A[D5] = "0".

6.5.1 RF-Receiving Abstract

Table 6-15 Receiving Function Abstracts

Item	Function				
RF-Receiving Frequency Band	315, 434, 868 / 915 MHz				
IF Frequency	IF = 230kHz, setting of IF Filter Bandwidth: wide = 320kHz IF = 280kHz, setting of IF Filter Bandwidth: middle = 270kHz Single conversion system (Using Image Cancel Mixer)				
Demodulation	FSK / ASK				
	FSK Demodulation	ASK Demodulation			
IF Detection	Delay Detection, Pulse Count Detection Envelope Detection				
Signal Detection	RSSI Detection, Noise Detection, Preamble Detection RSSI Detection, Preamble Detection				
Additional Function	NIR (Near Interference Rejection) Filter -				
Bit Rate Filter Cutoff Frequency	0.436kHz -19.78kHz (12 steps)				

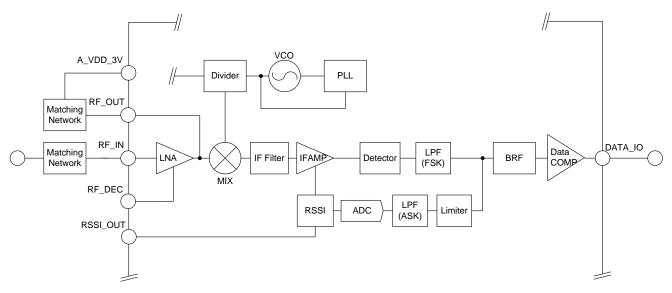


Fig 6-8 Receiver Block Diagram

6.5.2 Receiving Frequency Band

TC32306FTG is available following frequency bands, 315, 434, and 868/915 MHz.

6.5.3 Receiver Gain

Adjust overall gain of receiver block by matching network. The gain of LNA is controlled by the value of register: h'0E[D7:D6].

h'0E[D7] Lna_gain1	h'0E[D6] Lna_gain0	LNA Relative Gain (Reference value)
0	0	0 (Initial)
0	1	+0.8dB
1	0	+1.7dB
1	1	+2 5dB

Table 6-16 LNA Gain Control

Above are reference values at 315 MHz.

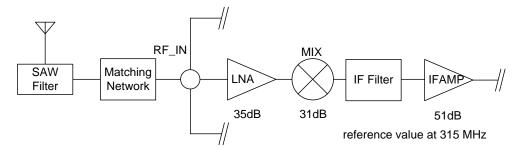


Fig 6-9 Receiver Gain Distribution

RF_IN pin is input of LNA. Input a RF signal via a suitable matching network. RF_OUT pin is output of LNA and open drain output. Supply voltage via a matching network. See the Evaluation Circuit for both input and output matching network. About RF_DEC pin, connect a capacitor (1000 pF (typ.)) and resister (100 Ω (typ.)), such as Fig 6-10 Typical LNA Network.

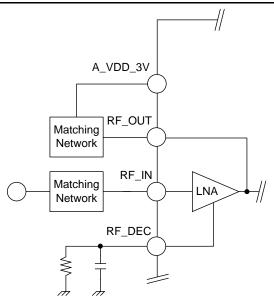


Fig 6-10 Typical LNA Network

6.5.4 IF Frequency

TC32306FTG has the single conversion system. The output of LNA is downconverted to IF frequency by Image Cancel Mixer. Set IF frequency with adequate IF filter bandwidth by setting of register.

Table 6-17 IF Frequency and Internal IF Filter Bandwidth

h'0E[D5] IFBW	IF Frequency	Internal IF Filter Bandwidth (Selected)
0	230kHz	320 kHz (typ.)
1	280kHz	270 kHz (typ.)

6.5.5 Demodulation

Select a type of demodulation (ASK or FSK) by the value of register: h'0A[D4]. Depending upon a type of demodulation, IF filter output signal has different path, RF detection and additional functions.

Table 6-18 Demodulations

h'0A[D5]RX_TX	h'0A[D4]FSK_ASK	Status
0	0	FSK (RX)
0	1	ASK (RX)
1	XX	TX

XX: About TX, see Table 6-30.

6.5.6 FSK Demodulation

To select FSK, set register: h'0A[D4] to "0" (FSK).

(1) NIR (Near Interference Rejection) Filter

Select the filter Enable/Disable by the value of register:h'10[D1]. This filter reduces a interfere signal near 300 kHz offset frequency. This filter is a notch type and the peak attenuation is about 20 dB. The notch frequency is selectable by the value of register:h'1B[D2:D1].

Table 6-19 Settings of NIR Filter

h'10[D1]NIR_Fil_en	h'1B[D2]NIR_Frqth1	h'1B[D1]NIR_Frqth0	Filter Enable/Disable & Notch Frequency
0	X	Х	Disable: -
1	0	0	Enable: 631 kHz
1	0	1	Enable: 659 kHz
1	1	0	Enable: 689 kHz
1	1	1	Enable: 712 kHz

X: Don't care

To use NIR filter (h'10[D1]NIR_Fil_en = "1"), Set following registers for the threshold level of NIR filter's detection (h'0D[D0], h'0F[D0], h'12[D1:D0], h'13[D0], h'1A[D0], h'1B[D0], h'1C[D2:D0]), according to the Detection selections (Delay Detection; h'10[D0]Sel_Det = "0" / Pulse Count Detection; h'10[D0]Sel_Det = "1"). Table 6-20 is a recommended setting by Toshiba.

Table 6-20 Settings of NIR Filter (Recommended Value)

h'10[D1] NIR_Fil_en	h'10[D0] Sel_Det	Register value for the threshold level of NIR filter's detection (Recommended value)					Detection	NIR Filter Performance (IC Application)			
0	-			D	on'	t care				-	-
		h'0F[D0]NIR_L2	1	h'1B[D0]NIR_2L1	1	h'0D[D0]NIR_H2	0	h'12[D0]NIR_2H1	0		After the interference
		h'1C[D1]NIR_L1	1	h'1C[D2]NIR_2L0	0	h'13[D0]NIR_H1	0	h'12[D1]NIR_2H0	0		is detected, NIR filter becomes valid and
	0	h'1C[D0]NIR_L0	0	-	-	h'1A[D0]NIR_H0	0	-	-	Delay	stays to it. (for intermittent RX)
	0	h'0F[D0]NIR_L2	1	h'1B[D0]NIR_2L1	1	h'0D[D0]NIR_H2	0	h'12[D0]NIR_2H1	0	Detection	Validity of NIR filter is
1		h'1C[D1]NIR_L1	1	h'1C[D2]NIR_2L0	0	h'13[D0]NIR_H1	0	h'12[D1]NIR_2H0	1		depending on the detection of the
		h'1C[D0]NIR_L0	0	-	•	h'1A[D0]NIR_H0	0	-	-		interference. (for continuous RX)
		h'0F[D0]NIR_L2	0	h'1B[D0]NIR_2L1	1	h'0D[D0]NIR_H2	0	h'12[D0]NIR_2H0	0	Pulse	
	1	h'1C[D1]NIR_L1	0	h'1C[D2]NIR_2L0	1	h'13[D0]NIR_H1	0	h'12[D1]NIR_2H1	0	Count	NIR filter is always valid.
		h'1C[D0]NIR_L0	0	-	-	h'1A[D0]NIR_H0	0	-	-	Detection	

(2) IF Detector

Select a type of IF Detections (Delay Detection / Pulse Count Detection) by the value of register:h'10[D0]. Select either detector suitable to the application. Both Delay Detection and Pulse Count Detection can convert input signal frequency (0-500 kHz) to voltage output. In Pulse Count Detection, over 500 kHz input signal frequency is converted to the voltage output equal to 500 kHz. In Delay Detection, the characteristic of S curve is mirror inverted at 500 kHz signal input. Select the High Frequency Detector by the value of register:h'0F[D4] in Delay Detection, over 500 kHz input signal frequency is converted to the voltage output equal to 500 kHz.

Table 6-21 Settings of IF Detector / High Frequency Detector

h'10[D0]Sel_Det	h'0F[D4]Hdet_en	Status
0	0	Delay Detection: High Frequency Detector Disable
0	1	Delay Detection: High Frequency Detector Enable
1	Х	Pulse Count Detection

X: Don't care

Notice:

- IF filter characteristics affects the maximum available signal frequency of High Frequency Detector.

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- High Frequency Detector Auto Off

After DET_out Signal is H level in Signal Detection function, High Frequency Detector will be automatically turned off by the setting of register: h'1A[D1] = "1". That may reduce the influence on RF receiver sensitivity. When both Delay Detection and High Frequency Detector are enabled (h'10[D0]Sel_Det = "0" and h'0F[D4]Hdet_en = "1"), this function is valid. To use this function again after Auto Off, set status to Battery Saving / Standby or digital block being disabled. This setting will be valid immediately after the data input to register: h'1A.

(3) LPF for FSK

The cutoff frequency of LPF for FSK is about 20 kHz.

(4) Signal Detections

In FSK, TC32306FTG is available 3 types of Signal Detections, RSSI Detection / Noise Detection / Preamble Detection. These Signal Detections have various sensitivity and accuracy, so select Signal Detection suitable to the application. Signal Detection parameters, such as Enable/Disable, detection interval, threshold level of detection and number times for judgment are set by register. These Signal Detections show signal situations as "Signal Detection" or "No Signal Detection" and these outputs depend on number of continuous times to be set in advance, which is above or below the threshold level.

Notice:

"Signal Detection" and "No Signal Detection" depend on TC32306FTG internal judgment. Those don't guarantee actual signal situations. It may be possible to be neither "Signal Detection" nor "No Signal Detection".

l	ı				
Item	RSSI Detection	Noise Detection	Preamble Detection		
Method	Monitoring integrated signal level at IF AMP.	Monitoring noise level near 34 kHz in FSK demodulation signal.	Monitoring preamble signal at Data COI output (Data pattern:10101), .		
Signal Detection Enable / Disable	h'0F[D7]Drssi_en 0:Disable / 1:Enable	h'0F[D5]Ndet_en 0:Disable / 1:Enable	h'0F[D6]Preamble_en 0:Disable / 1:Enable		
Detection Interval	h'1A[D7:D6 0.338 - 2.7n Cannot set RSSI detection and	ns (4steps)	h'1A[D2]Pre_DetTrig 0: signal period 1: signal bit		
Detection Threshold	h'16[D7:D0]DRSSI_Th70 h'19[D7:D2]Ndet_Th		Preamble detection Interval (512steps) h'18[D7]Pre_Time8/h'17[D7:D0]Pre_Time		
Level	8bit(256steps)	6bit(64steps)	Preamble detection error margin(128steps) h'18[D6:D0]Err_Margin60		
			h'1A[D4:D3]Pr	e_DetCount10	
Detection Number of Times for	One time detection	One time detection	Signal Detection	No Signal Detection	
judgment			3-6 period / 6-12bit(4steps)	3 period / 4 bit	
Signal Detection	above threshold. (RSSI_DET_out signal = "H")	below threshold. (NDET_out signal = "H")	,	in the error margin. _out signal = "H")	
No Signal Detection	Below threshold level.	Above threshold level.	out the error margin.		

⁻ Each results of Signal Detection (RSSI_DET_out signal / NDET_out signal / Preamble_DET_out signal) can be monitored in User Test. Each results of "No Signal Detection" cannot be monitored directly.

TC32306FTG outputs DET_out signal (Judgment of "Signal Detection") and Un_DET_out signal (Judgment of "No Signal Detection") to DET_TMONI1 pin and DET_TMONI2 pin, as the result of 3 overall signal detection judgment.

⁻ About each setting in detail, see "Register Overview & Description".

A) Additional Note of noise addition for high frequency signal

Noise Detection monitors noise level near 34 kHz in FSK demodulation signal. Therefore, both "Signal Detection" and "No Signal Detection" in Noise Detection function may be false because of the noise reduction caused by high frequency signal. To avoid this, TC32306FTG has an additional function to improve detection accuracy.

This function improves detection accuracy to add a constant value to detected noise level when input signal is high frequency. Set register:h'19[D0]Add_Hdet_en = "1" and this is valid. This function operates independently following register settings, Noise Detection (h'0F[D5]]Ndet_en), IF Detection (h'10[D0]Sel_Det) and High Frequency Detector (h'0F[D4]Hdet_en).

h'0F[D5] Ndet_en	h'19[D0] Add_Hdet_en	Function Status
0	0	Both Noise Detection and Noise Addtion for High Frequency Signal are not valid.
0	1	Noise Addtion for High Frequency Signal is valid. Noise Detection is not valid. "No Signal Detection" is operated, but "Signal Detection" is not operated.
1	0	Noise Detection is valid. Noise Addtion for High Frequency Signal is not valid.
1	1	Both Noise Detection and Noise Addtion for High Frequency Signal are valid

Table 6-23 Settings of Noise Addition for High Frequency Signal

Notice:

- In the settings of register: Ndet_en (h'0F[D5] = "0") and register: Add_Hdet_en (h'19[D0] = "1"), when High Frequency Signal is occupied in the half of RSSI / Noise detection interval set by register:[D7:D6]Ntime1..0, the register of Noise Signal Level Monitor (h'23[D7:D0]DNDET7..0) outputs "d'40". When High Frequency Signal is occupied in the full of RSSI / Noise detection interval, the register of Noise Signal Level Monitor (h'23[D7:D0]DNDET7..0) outputs "d'81".
- Noise Addition for High Frequency Signal can be valid in Pulse Count Detection and Delay Detection.
- Noise Addition for High Frequency Signal can be valid even if High Frequency Detector is not valid in Delay Detection.

B) Additional Note of Preamble Detection

The function of Preamble Detection checks signal by counting the number of clocks between the rising edges, or between the falling edge and the rising edge of output signal from Data COMP circuit. If the number of clocks is counted within the set value +/- error margin (h'18[D6:D0]), this signal is recognized as Preamble signal. The clock frequency is twice by the internal clock using in Bit Rate Filter. About internal clock frequency, see Table 6-25.

Notice: 1

- When the function of Preamble Detection checks signal by counting the number of clocks between the rising edges (h'1A[D2] = "0"), the number of count is as same as the setting value of register: Pre_Time8..0.
- When the function of Preamble Detection checks signal by counting the number of clocks between the rising edge and the falling edge (h'1A[D2] = "1"), the number of count is half of the setting value of register: Pre_Time8..0 is odd, half of this setting value is rounded down to the integer.
- Both signal counting the number of clocks between the rising edges (h'1A[D2] = "0") and between the rising edge and falling edge (h'1A[D2] = "1"), error margin is as same as the setting value of register: Err_Margin6..0.

Way of setting:

- Setting value: Pre_Time8..0(h'18[D7],h'17[D7:D0])
- Error margin: Err_Margin6..0(h'18[D6:D0])
- The number of clocks: $Pre_Time8..0 = (2 \text{ x fbc})/fp$
- fp: preamble signal cycle frequency

- fbc: internal clock frequency, fixed by Bit Rate Filter setting (h'0E[D4:D1]BRF_Bit3..0)
- Error margin is as same as the setting value of register: Err_Margin6..0.

- Calculation example

fp = 600Hz

fbc = 23.69kHz (Set the cutoff frequency of Bit Rate Filter as 619Hz)

Pre_Time8..0 = $(2 \times 23.69) / 0.6 = 78.9 \rightarrow 79(h'18[D7], h'17[D7:D0] = b'001001111)$

If the number of clocks is within "79±Err_Margin6..0". RF receiving signal will be recognized as Preamble signal.

Notice: 2

When to use the function of AutoOff Type A with using Preamble Detection, set both Data Comparator Quick Charge 1 and 2 to the status of ON.

(In the settings of register: AutoOffA_en (h'10[D5] = "1") and register: Preamble_en (h'0F[D6] = "1"), set register: Data Comparator Quick Charge 1 (h'10[D7] = "1") and register: Data Comparator Quick Charge 2 (h'10[D6] = "1").)

If not set above, the function of AutoOff Type A may fail an expected operation. As the result, this IC can't continue enough signal detection period and an valid data can't be get in some.

6.5.7 ASK Demodulation

To select ASK, set register: h'0A[D4] to "1"(ASK).

(1) RSSI

Detect the level of IF signal.

(2) AD converter (ADC)

Digitize the level of IF signal detected by RSSI.

(3) LFP (ASK)

The cutoff frequency of LPF (fc) is about 40 kHz.

(4) Limiter (This is only valid to use the function of Data Comparator Quick Charge 2.)

This is only valid to use the function of Data Comparator Quick Charge 2 in the

This is only valid to use the function of Data Comparator Quick Charge 2 in the subsequent Data Comparator circuit. RSSI signal voltage through LPF is kept over the internal setting value in Limiter circuit. Limit level is calculated with the peak voltage in the sequential. The peak voltage is detected in Peak Hold Circuit in the subsequent of Bit Rate Filter.

- Peak Hold Circuit

Peak Hold Circuit outputs peak voltage to track its input (Bit Rate Filter output) with time constant that is fast at the rising of the input signal and that is slow at the falling of the input signal. The time constants are tp'/fbc at charging and tr/fbc at discharging.

- * fbc: internal clock frequency set by Bit Rate Filter, register: h'0E [D4:D1]BRF_Bit3..0
- * tp': inverse number of 1/tp + 1/tr
- * tp: peak hold voltage charge coefficient, register:h'1C [D4:D3] Peak_Charge1..0
- * tr: peak hold voltage discharge coefficient, register:h'1C [D7:D5] Peak Ref2..0

When TC32306FTG starts to Run status, Peak Hold Circuit output voltage will reach 90% of the peak voltage during "tp' / fbc x 2.30[s]".

Table 6-24 Setting of Peak Hold Circuit

Input Signal of Peak Hold Circuit	Status	Register to set time constant
During the signal rising	Viph - voph ≥ 0	h'1C[D4:D3]Peak_Charge10 h'1C[D7:D5]Peak_Ref20
During the signal falling	Viph - voph < 0	h'1C[D7:D5]Peak_Ref20

Viph: Input voltage of Peak Hold Circuit Voph: Output voltage of Peak Hold Circuit Notice:

- Must not set the value of tp (set by register:h'1C [D4:D3] Peak_Charge1..0) smaller than the value of Quick Charge Coefficient (set by register:h'1B[D7:D6]Charge2_Ref1..0).
- Set the value of tp (set by register:h'1C [D4:D3] Peak_Charge1..0) much smaller than the value of tr (set by register:h'1C[D7:D5]Peak_Ref2..0).
- The peak hold level can be monitored at the register:h'1F[D7:D0]PEAK7..0.
- Limiter will be bypassed when Data Comparator Quick Charge 2 is not used.

(5) Signal Detection

In ASK, TC32306FTG is available 2 types of detections, RSSI Detection / Preamble Detection. Those detections are as same as that in FSK. Noise Detection cannot be available in ASK.

6.5.8 Bit Rate Filter

The cutoff frequency of Bit Rate Filter can be available in 12 steps between 0.436 kHz and 19.78 kHz by the setting of register:h'0E[D4:D1]. Select and set suitable cutoff frequency regarding demodulated signal data rate. There are different characteristic of LPF in ASK or FSK. Set the cutoff frequency with considering them.

The cutoff frequency is only for Bit Rate Filter. Set it to consider the influence of LPF (FSK: fc = 20kHz, ASK: fc = 40 kHz) of the previous circuit.

Table 6-25 Settings of Bit Rate Filter and Cutoff Frequency including LPF

h'0E[D4] BRF_Bit3	h'0E[D3] BRF_Bit2	h'0E[D2] BRF_Bit1	h'0E[D1] BRF_Bit0	Cutoff Frequency (fc)	requency the previous LPF		Internal Clock (fbc)
					FSK	ASK	
0	0	0	0	19.8 kHz	14.1 kHz	17.8 kHz	758 kHz
0	0	0	1	14.0 kHz	11.5 kHz	13.2 kHz	758 kHz
0	0	1	0	9.90 kHz	8.91 kHz	9.62 kHz	379 kHz
0	0	1	1	6.98 kHz	6.60 kHz	6.88 kHz	379 kHz
0	1	0	0	4.95 kHz	4.81 kHz	4.91 kHz	189 kHz
0	1	0	1	3.49 kHz	3.44 kHz	3.47 kHz	189 kHz
0	1	1	0	2.48 kHz	2.46 kHz	2.47 kHz	94.8 kHz
0	1	1	1	1.74 kHz	1.74 kHz	1.74 kHz	94.8 kHz
1	0	0	0	1.24 kHz	1.24 kHz	1.24 kHz	47.4 kHz
1	0	0	1	0.872 kHz	0.872 kHz	0.872 kHz	47.4 kHz
1	0	1	0	0.619 kHz	0.619 kHz	0.619 kHz	23.7 kHz
1	0	1	1	0.436 kHz	0.436 kHz	0.436 kHz	23.7 kHz
1	1	0	0	19.8 kHz	14.1 kHz	17.8 kHz	758 kHz
1	1	0	1	14.0 kHz	11.5 kHz	13.2 kHz	758 kHz
1	1	1	0	19.8 kHz	14.1 kHz	17.8 kHz	758 kHz
1	1	1	1	14.0 kHz	11.5 kHz	13.2 kHz	758 kHz

Notice:

The cutoff frequency and the Internal Clock of Bit Rate Filter are derived from 30.32MHz Reference Clock Frequency.

6.5.9 Data Comparator

Data Comparator shapes the waveform of the demodulated output signal of Bit Rate Filter, and

outputs the result signal to DATA_IO pin. That demodulated signal is inverted from modulated signal.

(1) Reference Voltage

The reference voltage of Data Comparator (vref) is determined by the value tracking input voltage of Data Comparator (vi) with slow time constant. The time constant is nr / fbc, and nr is set by register:h'1B[D5:D3]Cmp_Ref2..0. Set it suitable with considering the signal data rate or coding.

Time constant = nr / fbc

* fbc: internal clock frequency set by Bit Rate Filter, register:h'0E [D4:D1]BRF_Bit3..0

The duty of Data Comparator output will be worse, due to the large fluctuation of vref caused by setting of unsuitable time constant or number of consecutive data with the same sign. Then suitable time constant can be simply calculated by the following equation. In the equation, vdiff[%] is fluctuation of vref and t is a maximum number of consecutive data of the same sign minus 1.

- Way of Setting

Time constant = nr / fbc = t / -ln(1 - vdiff / 100)

- Calculation Example

Data Rate = 600 Hz

fbc = 23.69 kHz (Set the cutoff frequency of Bit Rate Filter as 619 Hz.)

fluctuation of vref = 10%

The number of consecutive data with the same sign: 4

 $t = (4-1) / (2 \times 600) = 0.0025s$

nr/fbc = 0.0025 / (-ln(1-10/100)) = 0.0237

nr = 0.0237 x 23690 = 561.45

Suitable setting value of register: h'1B [D5:D3] is b'100(nr=512). This value is the nearest of 561.45.

The average of vref can be monitored from register: h'21[D7:D0]Ref_bias7..0 and the fluctuation of vref can be monitored from register:h'20[D7:D0]Ref_diff7..0. Also vref can be monitored from DET_TMONI3 or 4 pin. Because the time constant set by Data Comparator Reference Voltage Charge Coefficient (h'1B[D5:D3]Cmp_Ref2..0) is slower than the signal data rate, the rising time of the signal will be taken long. Data Comparator output voltage will reach 90% of vref with "nr / fbc x 2.30". To shorten rising time of the signal, use the function of Data Comparator Quick Charge 1 or 2.

(2) Data Comparator Quick Charge 1 (During a certain period)

The function is able to shorten the start period of TC32306FTG because time constant of vref will change to 1/16 or 1/4 only during that period. During start period, the output signal duty will be worse than that during normal condition, but Data Comparator output is obtained faster than the condition without Quick Charge 1. After finishing the certain period, the output signal duty will be improved because the time constant becomes nr / fbc (Normal condition).

Table	6-26	Ouick	Charge	1
Table	0-20	Wuick	Charue	

	Functional Period of	Normal		
	The Fastest	Faster	rtormai	
Time Constant	(nr / fbc) x 1/16	(nr / fbc) x 1/4	nr / fbc	
Validity Period	(nr / 4) / fbc	(nr / 2) / fbc	=	

The time constant is switched as the Fastest → Faster → Normal.

(3) Data Comparator Quick Charge 2 (Tracking to correspond to the voltage difference)

When the difference between the reference voltage of Data Comparator (vref) and the input voltage of it is larger than preset voltage threshold level (vth), the vref will track the vi as following time constant.

When the difference between vref and vi is large such as in the start period, Data Comparator output is obtained faster than the condition with Quick Charge 1.

Time constant = nr' / fbc

Data Comparator output voltage will reach 90% of vref with "nr / fbc x 2.30[s]".

*nr': inverse number of (1/nr + 1/nc)

*nr: Data Comparator Reference Voltage Charge Coefficient (Set by register:h'1B[D5:D3]Cmp_Ref2..0.)

Table 6-27 Quick Charge 2

	Value of vi – vref	Time Constant
Functional Period of Quick Charge 2	vi - vref ≥ vth	nr' / fbc
Normal	vi - vref < vth	nr / fbc

The threshold level (vi – vref) is set according to FSK deviation. When the threshold level is same or smaller than that deviation, receiver sensitivity will be worse because of signal noises around the level of receiver sensitivity. When the threshold level is larger than that deviation, the rising time of signal will be taken longer. Check signals in User Test to set the threshold level as suitable. The threshold level is set by register:h'11[D7:D0]Charge2 Th7..0.

- Calculation Example of the threshold level
The case to set register:h'11 [D7:D0]Charge2_Th7..0 = 61 (b'00111101)
61 / 1.53 = 39.9 → equivalent ±39.9kHz

1.53 is a constant.

(4) DATA_IO pin control

DATA_IO pin outputs the demodulated signal. DATA_IO pin output can be controlled by the result of Signal Detection by setting register: h'0F[D3].

Table 6-28 Data_IO Pin Control

h'0A[D5] RX_TX	h'0F[D3] Dataout_cnt_en	DET_out Signal	Pin Behavior
0	0	X	Output demodulated signal
0	1	L→H	Output demodulated signal
1	X	X	Input pin for TX

X: Don't care

Notice:

- The register: h'0F[D3]Dataout_cnt_en is valid in RX.
- When the register: h'0F[D3] = "1", TC32306FTG will output demodulated signal from the first rising edge of DET_out signal. Till the first rising edge of DET_out signal, this IC outputs "L".
- When the register: h'0F[D3] = "1" and DET_out signal changes from "L" to "H", this IC outputs demodulated signal in spite of the condition of DET_out signal till this IC will be Battery Saving or Standby mode.
- When the register:h'0F[D3] = "1" and non use of Signal Detections, this IC doesn't output demodulated signal. (Fixed "L" output.)

6.6 RF Transmitter

For RF-Transmitting, set register:h'0A[D5] = "1".

^{*}nc: Quick Charge Coefficient (Set by register: h'1B[D7:D6]Charge2_Ref1..0.)

6.6.1 RF-Transmitting Abstract

Table 6-29	RF-Transmit	tina Function	Abstracts
Table 0-23	1XI - 11 ali 511111	uniq i uncuon	ADSHACIS

ltem	Function	
Modulation	FSK / ASK	
Deviation (FSK)	Unmodulated - +/-105 kHz (315MHz Band) Unmodulated - +/-157.5 kHz (434MHz Band) Unmodulated - +/-315kHz (868 / 915MHz Band) * 64 steps in each frequency band. (Including unmodulated)	
RF-Transmitting Frequency Band	315, 434, 868 / 915 MHz	
Output Level	Coarse: 4 steps Fine: 16 steps	

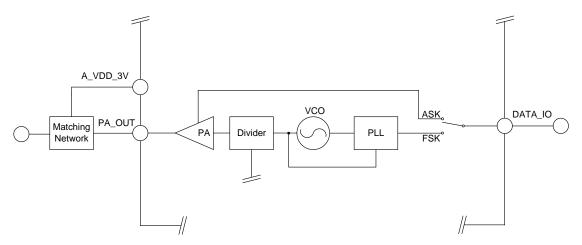


Fig 6-11 Transmitter Block Diagram

6.6.2 RF Signal Modulation

TC32306FTG is available 2 modulation, FSK and ASK to be set by register: h'0A[D4].

Table 6-30 RF Signal Modulation

h'0A[D5]RX_TX	h'0A[D4]FSK_ASK	Modulation
0	XX	RX
1	0	FSK (TX)
1	1	ASK (TX)

XX: About RX, see Table 6-18

6.6.3 FSK Modulation

To select FSK, set register:h'0A[D4] to "0"(FSK). TC32306FTG operates FSK modulation at PLL block with DATA_IO pin input signal. In FSK setting, the deviation is set by the register:h'12[D7:D2]Dev5..0. Available frequency deviation steps are different at each RF frequency band.

h'12[D7]	h'12[D6]	h'12[D5]	h'12[D4]	h'12[D3]	h'12[D2]		Devi	ation after divide	d (fdev)
Dev5	Dev4	Dev3	Dev2	Dev1	Dev0	n	315 MHz nd = 6	434 MHz nd = 4	868 / 915MHz nd = 2
0	0	0	0	0	0	0	Unmodulated	Unmodulated	Unmodulated
0	0	0	0	0	1	1	+/-1.67 kHz	+/-2.50 kHz	+/-5.00 kHz
0	0	0	0	1	0	2	+/-3.33 kHz	+/-5.00 kHz	+/-10.00 kHz
0	0	0	0	1	1	3	+/-5.00 kHz	+/-7.50 kHz	+/-15.00 kHz
0	0	1	1	0	0	12	+/-20.00 kHz	+/-30.00 kHz	+/-60.00 kHz
1	1	1	1	0	1	61	+/-101.67 kHz	+/-152.50 kHz	+/-305.00 kHz
1	1	1	1	1	0	62	+/-103.33 kHz	+/-155.00 kHz	+/-310.00 kHz
1	1	1	1	1	1	63	+/-105.00 kHz	+/-157.50 kHz	+/-315.00 kHz

Deviation after divided: fdev= (fd/nd)×n

fd: Frequency Resolution of VCO $10 \, \text{kHz}$ (= fosc / 3032) * fosc: Reference Clock Frequency ($30.32 \, \text{MHz}$) nd: Division Ratio (nd = 6 for $315 \, \text{MHz}$ Band, nd=4 for $434 \, \text{MHz}$ Band, nd = 2 for $868 \, / \, 915 \, \text{MHz}$ Band) n: the value set by register: h'12 [D7:D2]Dev5..0. 0-63 (Converted to decimal.)

6.6.4 ASK Modulation

To select ASK, set register: h'OA[D4] to "1"(ASK). TC32306FTG operates ASK modulation by setting ON and OFF to RF-Transmitting Power Amplifier (PA) with DATA_IO pin input signal. If PA is enabled (See Table 6-33.), PA output is shown as table 6-32.

Table 6-32 PA Output and Input Logic (ASK)

DATA_IO Input Logic	PA Output
0	OFF
1	ON

6.6.5 TX Output

PA outputs modulated signal to an antenna.

(1) RF-Transmitting Power Amplifier (PA)

PA output (PA_OUT pin) is an open drain output. Connect a voltage supply (A_VDD_3V pin) via a matching circuit. PA is operated by the combination of register:h'0A[D5]RX_TX, register:h'13[D1]PA_en and internal lock detect signal (LD signal). LD signal is an internal signal only for PA, and it will keep high level after the first rising edge of PLL_LD signal which is monitored from DET_TMONI1/2 pin.

Table 6-33 Behavior of PA

h'0A[D5] RX_TX	h'13[D1] PA_en	Internal LD Signal	PA behavior
0	Х	Х	Disable
1	Х	L	Disable
1	0	Х	Disable
1	1	Н	Enable

X: Don't care

Internal LD Signal is only use for PA, and the signal keeps "H" after the first rising edge of PLL_LD Signal. Above function is only available in TX and Internal LD Signal cannot be monitored. To release

the signal holding state, set one of the follows.

- Set TC32306FTG in the status of Battery Saving or Standby.
- Change from TX to RX.
- Change TX modulation. (ASK \leftrightarrow FSK)
- Change RF frequency. (In the change in the value of register "h'0B" and/or "h'0C")
- Change the value of register:h'12[D7:D2] for TX deviation. (This is only valid in FSK setting (h'0A[D4]FSK_ASK = "0"))

Notice:

- PA will continue to operate even though PLL_LD signal will be "L" because Internal LD Signal still keeps to be "H".
- In PA operation, keep its load condition suitable, and that load condition must not be open or short.
- Only use for RX, keep PA_OUT pin to be open, and this IC must not be set to TX.
- Must not change RF-Transmitting Frequency Band (register: h'0A[D1:D0]) alone during TX. It may cause of unexpected radiation because the keeping of Internal LD Signal level is not released.

(2) Output level

The output level is controlled 2 types of step (Coarse, Fine) independently by register.

Table 6-34 Example of PA Output Level (Coarse)

h'13[D3] TX_gain1	h'13[D2] TX_gain0	Output Level Variation Width (Reference value)
0	0	-10.1dB
0	1	-5.3dB
1	0	-2.0dB
1	1	0dB (Initial)

Above are reference values at 315 MHz Band.

Table 6-35 Example of PA Output Level (Fine)

h'13[D7] TX_subgain3	h'13[D6] TX_subgain2	h'13[D5] TX_subgain1	h'13[D4] TX_subgain0	Level Settings
0	0	0	0	Minimum
1	1	1	1	Maximum (Initial)

The reference level of each PA output settings are indicated in Fig 6-12. The output level steps are different from frequency band or TX_gain settings.

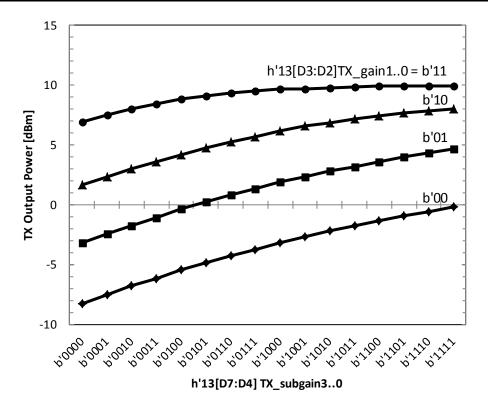


Fig 6-12 Output Level Settings (Reference Value)

6.7 Control System and Mode

6.7.1 Control System and Mode Abstract

Table 6-36 Control System and Mode Abstracts

Item	Mode / Function / pins
Way of Control	external pins, serial data control
External Pin	RESET pin, ENB pin
Control Method	SPI (Single Read/Write, Burst Read/Write), EEPROM
Control Mode	Normal / User Test

6.7.2 **SPI Mode**

MCU and TC32306FTG are connected by SPI lines and MCU controls this IC.

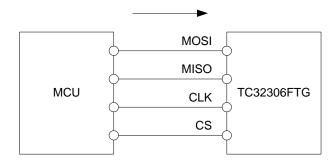


Fig 6-13 Conceptual Connection of SPI Control

33

In SPI Mode, TC32306FTG is available Single Read/Write and Burst Read/Write. These are selected from SPI instruction data.

Table 6-37 Single Read/Write and Burst Read/Write

Function	Explanation
Single Read/Write	To read and write only specified address register data. It is available for accessing to single or non-continuous address registers.
Burst Read/Write	To read and write in order from the specified address register data. It is available for accessing to continuous address registers. To specify the start address only causes to shorten the read/write time.

6.7.3 SPI Control Data Format

SPI control data format of TC32306FTG is constructed by instruction (8 bit), address (8 bit) and data (8 bit).



Fig 6-14 SPI Control Data Format

In SPI Mode, Single / Burst, Write / Read and Confirmation of written data are set by instruction data. Enter each SPI control data sequentially from most significant bit (MSB).

Table 6-38 Type of SPI Instructions and Settings

SPI Control		17	16	15	14	13	12	l1	10
Single Read/Write	Write	0	0	0	0	Χ	1	1	0
	Read		0	0	0	Χ	1	1	1
Burst Read/Write	Write		0	0	0	Χ	0	1	0
	Read		0	0	0	Χ	0	1	1
	Confirmation of written data		0	0	0	Χ	1	0	1
Stop SPI Function		Except above data							

^{*} x: 0 or 1

 $^{^{\}star}$ Stop SPI Function: After entering SPI instruction data, subsequent data input will be invalid. To enable the input data again, enter SPI instruction data correctly after CS pin is set to be "H" once.

6.7.4 SPI Single Read/Write

(1) Write

Set the single Read/Write (Write) data pattern to the instruction area. Set to register address to the next 8 bit, then register data to after next 8 bit. To write other address registers' data continuously, repeat above routine. After input of 24 bit data (Instruction, address and data), the register value is updated. The register data from MOSI pin is written when CS pin is "L" and CLK signal is at the rising edge.

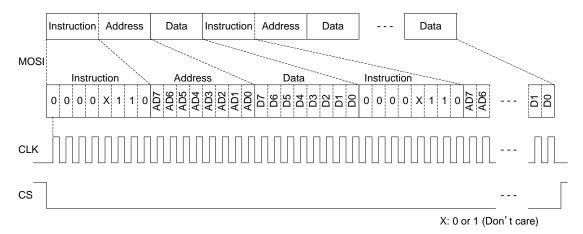


Fig 6-15 Write Format (SPI Single Read/Write)

(2) Read

Set the single Read/Write (Read) data pattern to the instruction area. Set to register address to the next 8 bit to read that data. After input the address, MISO pin outputs 8 bit data from the specified register. After output that 8 bit data, repeat above routine to read other address data continuously. During data read from MISO pin, MOSI pin does not accept input data. MISO pin outputs the register data when CS pin is "L" and CLK signal is at the falling edge.

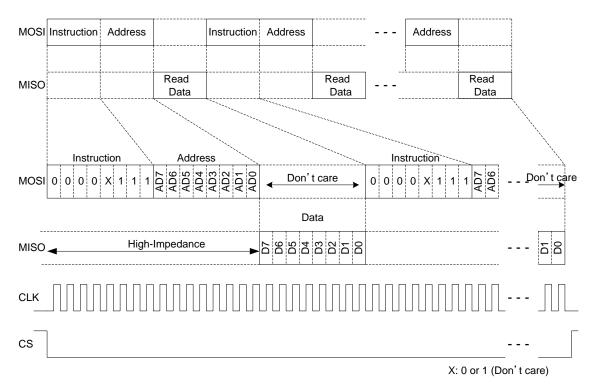


Fig 6-16 Read Format (SPI Single Read/Write)

6.7.5 SPI Burst Read/Write

(1) Write

This function continuously writes data to the order from the specified address. Set the burst Read/Write (Write) data pattern to the instruction area. Set to start register address to the next 8 bit, then register data to after next 8 bit. After that, repeat sequentially to set only 8 bit register data to the order. After every input of 8 bit data, the register value is updated. The register data from MOSI pin is written when CS pin is "L" and CLK signal is at the rising edge. Not to write unnecessary data to the following address, set CS pin to be "H" as soon as possible after writing all of the data.

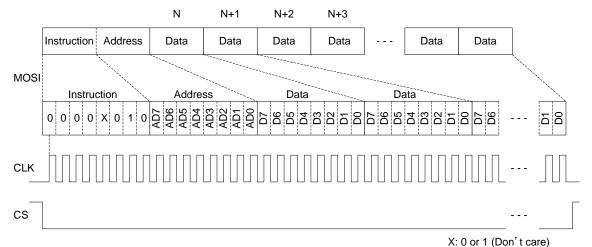


Fig 6-17 Write Format (SPI Burst Read/Write)

Notice: To change the instruction or start register address, once set CS pin to be "H" in the burst

(2) Read

Read/Write.

This function continuously reads data to the order from the specified address. Set the burst Read/Write (Read) data pattern to the instruction area. Set to start register address to the next 8 bit to read that data. After input the address, MISO pin outputs 8 bit data from the specified register. To stop or finish reading data, set CS pin to be "H".

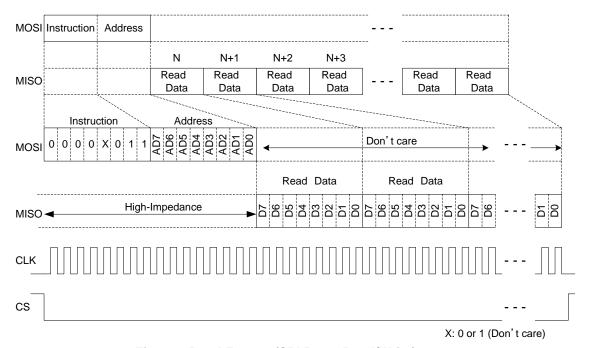


Fig 6-18 Read Format (SPI Burst Read/Write)

- After reading data reaches the last register address (h'FF), TC32306FTG continues to output data from the beginning address (h'00).
- During outputting register value from MISO pin, MOSI pin does not accept input data.
- To change the instruction or start register address, once set CS pin to be "H" in the Burst Read/Write.

(3) Confirmation of written data

This function continuously writes data to the order from the specified address and confirms the written data.

Notice:

- This function is not intended to read the data inside the register. Use Single/Burst Read mode to confirm the data inside the register.

Set the Burst Read/Write (Confirmation of written data) data pattern to the register instruction area. Set same as the Burst Read/Write (Write) and input. The input data is output from MISO pin with 8 bit delay after the address area. The data writing is valid till the rising edge of CS signal, and the data reading is finished at the rising edge of CS signal.

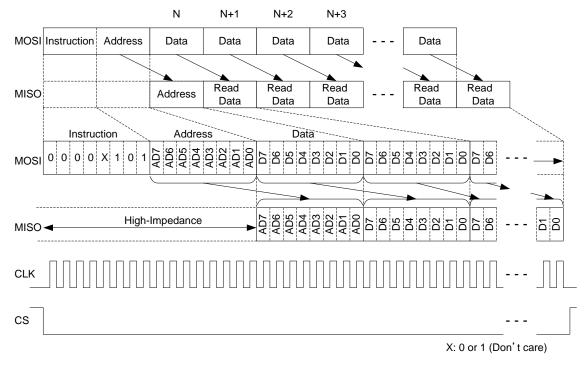


Fig 6-19 Confirmation of Written Data Format (SPI Burst Read Write)

(The number of write data is same as that of read data.)

6.7.6 SPI Mode Signal Timings

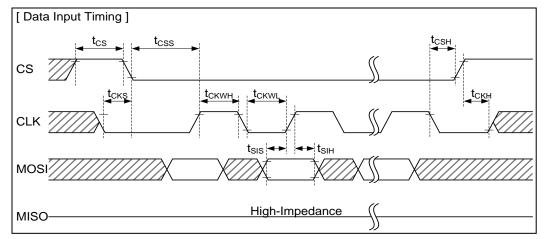


Fig 6-20 Example of SPI Write Timing

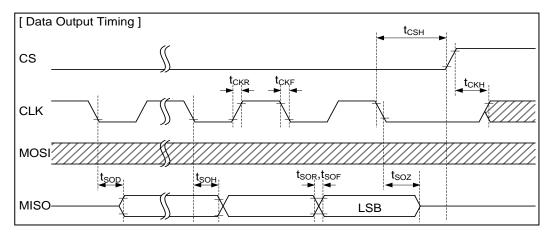


Fig 6-21 Example of SPI Read Timing (Single Read/Write)

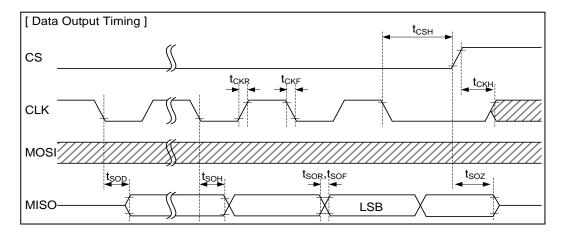


Fig 6-22 Example of SPI Read Timing (Burst Read/Write)

The timing chart for explaining the operation of features and may have been simplified.

Item	Code	Min	Тур.	Max	Unit
CLK Frequency	f _{ck}	-	-	3.0	MHz
CLK "H" Time	t _{CKWH}	100	-	-	ns
CLK "L" Time	t _{CKWL}	100	-	-	ns
CLK Setup Time	t _{CKS}	40	-	-	ns
CLK Hold Time	t _{CKH}	40	-	-	ns
CLK Rising Time	t _{CKR}	-	-	10	ns
CLK Falling Time	t _{CKF}	-	-	10	ns
CS "H" Time	t _{CS}	40	-	-	ns
CS Setup Time	t _{CSS}	30	-	-	ns
CS Hold Time	t _{CSH}	100	-	-	ns
MOSI Setup Time	t _{SIS}	30	-	-	ns
MOSI Hold Time	t _{SIH}	30	-	-	ns
MISO Delay Time *	t _{SOD}	-	-	100	ns
MISO Hold Time *	t _{SOH}	-	-	100	ns
MISO Disable Time *	t _{SOZ}	-	-	30	ns
MISO Rising Time *	t _{SOR}	-	-	50	ns
MISO Falling Time *	t _{SOF}	-	-	50	ns

Table 6-39 SPI Mode Timing

6.7.7 EEPROM Mode

EEPROM and MCU, connect via TC32306FTG. This IC is controlled by the register data of EEPROM. Select up to 8 configuration that are made as registers' modules from "h'0A" to "h'1C", depending on the size of EEPROM. In this mode, use of pins and external connections are different from those of SPI Mode. For example, TX_SW / RX_SW / ENB pin are used to select configuration of EEPROM. Must not set MODE2 pin to "L" (= for SPI Mode) at the circuit connection for EEPROM Mode.

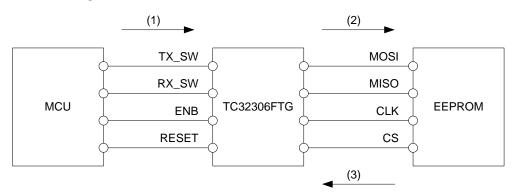


Fig 6-23 Conceptual Connection MCU, EEPROM and TC32306FTG

- In advance, write registers' values to each configuration data area of EEPROM.
- MCU commands this IC for selecting configuration data area of EEPROM. (1)
- This IC read a configuration data from EEPROM by SPI lines at the rising edge of RESET pin signal. (2)
- This IC is operated depending on EEPROM data. (3)

- Majority logic

In EEPROM Mode, the majority logic is adopted to reduce the probability of unexpected operation due to data corruption of EEPROM. Each configuration has 3 sets of data area in EEPROM, and this IC read them. Then the data values are decided by a majority vote of each bit. In advance, three same data should be written in each configuration to the specified address of EEPROM. The relation

^{*} Time values of MISO are derived at the load capacitance of 10pF.

between EEPROM address and the register address of this IC are shown in Table 6-40.

6.7.8 EEPROM Control Data Format

In EEPROM Mode, TC32306FTG operates Burst Read for the EEPROM. The configuration is selected by the combination of TX_SW pin, RX_SW pin and ENB pin.

Notice:

- The memory size of 1 k, 2 k and 4 k bit are available for EEPROM. The configuration of 2,4 and 8 are available respectively.
- Select EEPROM adapted for Burst Read.
- The serial clock (= CLK pin output signal) to read EEPROM data generated by the inner oscillator of TC32306FTG is frequency of about 2 MHz. Select EEPROM adapted for that frequency.
- (1) Set the configuration with TX_SW pin, RX_SW pin and ENB pin from MCU. Then set RESET pin is "H". (= The reset is released.) The configuration change is available all the time, however the operation is valid at the timing of change of RESET pin from "L" to "H".
- (2) TC32306FTG operates Burst Read to the first set data area of EEPROM through SPI lines. Burst Read operates from the start address till the end address of the configuration data sequentially. After the reading, this IC starts to Run as the configuration of first set data area.
- (3) This IC operates Burst Read to the second and third set data area continuously, then the register setting is fixed by majority logic.
- (4) This IC runs depending on the register: h'0A[D6]ACT.

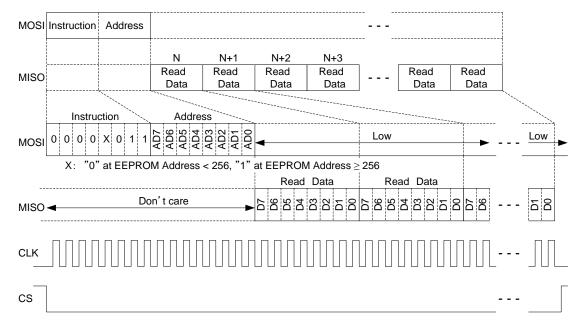


Fig 6-24 Read Format from EEPROM (EEPROM Mode)



Table 6-40 Relation between EEPROM and TC32306FTG Register Address

Confin		Pin Name		Read				FEDD	ON4 ^	ddre					DOM.	Ci	
Config.	RX_SW	TX_SW	ENB	Order				EEPK	OIVI A	ddress				EEF	EEPROM Size		
				1 st	0	1	2	3		15	16	17	18				
Config.1	0	0	0	2 nd	20	21	21	23		35	36	37	38				
				3 rd	40	41	42	43		55	56	57	58	ds)			
				1 st	64	65	66	67		79	80	81	82	1k-bit(128words)			
Config.2	0	0	1	2 nd	84	85	86	87		99	100	101	102	it(128			
				3 rd	104	105	106	107		119	120	121	122	1k-bi			
				1 st	128	129	130	131		143	144	145	146				
Config.3	0	1	0	2 nd	148	149	150	151		163	164	165	166				
				3 rd	168	169	170	171		183	184	185	186		ds)		
				1 st	192	193	194	195		207	208	209	210		2k-bit(256words)		
Config.4	0	1	1	2 nd	212	213	214	215		227	228	229	230		it(256		
				3 rd	232	233	234	235		247	248	249	250		2k-b		
				1 st	256	257	258	259		271	272	273	274				
Config.5	1	0	0	2 nd	276	277	278	279		291	292	293	294				
				3 rd	296	297	298	299		311	312	313	314				
				1 st	320	321	322	323		335	336	337	338				
Config.6	1	0	1	2 nd	340	341	342	343		355	356	357	358				
				3 rd	360	361	362	363		375	376	377	378				
				1 st	384	385	386	387		399	400	401	402				
Config.7	1	1	0	2 nd	404	405	406	407		419	420	421	422				
				3 rd	424	425	426	427		439	440	441	442			ds)	
<u> </u>				1 st	448	449	450	451		463	464	465	466			4k-bit(512words)	
Config.8	1	1	1	2 nd	468	469	470	471		483	484	485	486			it(51;	
				3 rd	488	489	490	491		503	504	505	506			4k-b	
-	TC32306FT	G Register	Address		h'0A	h'0B	h'0C	h'0D		h'19	h'1A	h'1B	h'1C				

6.7.9 EEPROM Mode Signal Timings

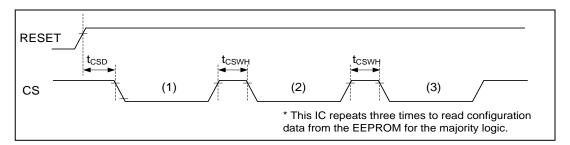


Fig 6-25 Example of EEPROM Control Timing

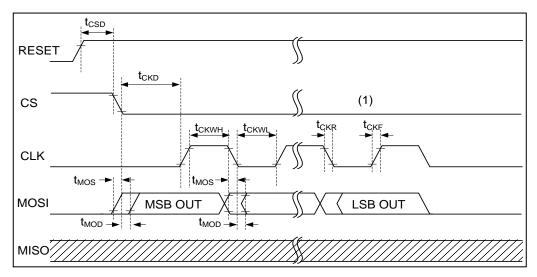


Fig 6-26 Example of EEPROM Output Timing

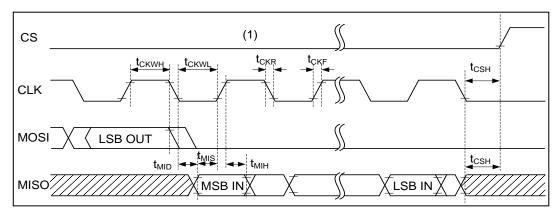


Fig 6-27 Example of EEPROM Input Timing

The timing chart for explaining the operation of features and may have been simplified.

Table 6-41 EEPROM Mode Timing (COM_VDD = 3.0 - 5.5V)

Item	Code	Min	Тур.	Max	Unit
CLK Frequency *	luency * f _{ck}		2.0	3.0	MHz
CLK "H" Time *	t _{CKWH}	125	-	-	ns
CLK "L" Time *	t _{CKWL}	125	-	-	ns
CLK Rising Time *	t _{CKR}	-	-	50	ns
CLK Falling Time *	t _{CKF}	-	-	50	ns
CLK Delay Time *	t _{CKD}	150	-	-	ns
CS Delay Time *	t _{CSD}	400	-	-	ns
CS "H" Time *	t _{CSWH}	500	-	-	ns
CS Hold Time *	t _{CSH}	100	-	-	ns
MOSI Preceding Time *	t _{MOS}	-	-	50	ns
MOSI Delay Time *	t _{MOD}	-	-	50	ns
MISO Delay Time	t _{MID}	-	-	90	ns
MISO Setup Time	t _{MIS}			10	ns
MISO Hold Time	t _{MIH}	-	-	100	ns

^{*} Time values of CLK, MISO and MOSI are derived at the load capacitance of 10pF.

Table 6-42 EEPROM Mode Timing (COM_VDD = 2.5 - 3.0V)

ltem	Code	Min	Тур.	Max	Unit
CLK Frequency *	f _{ck}	1.0	2.0	3.0	MHz
CLK "H" Time *	t _{CKWH}	150	-	-	ns
CLK "L" Time *	t _{CKWL}	150	-	-	ns
CLK Rising Time *	t _{CKR}	-	-	50	ns
CLK Falling Time *	t _{CKF}	-	-	50	ns
CLK Delay Time *	t _{CKD}	150	-	-	ns
CS Delay Time *	t _{CSD}	400	-	-	ns
CS "H" Time *	t _{CSWH}	500	-	-	ns
CS Hold Time *	t _{CSH}	100	-	-	ns
MOSI Preceding Time *	t _{MOS}	-	-	50	ns
MOSI Delay Time *	t _{MOD}	-	-	50	ns
MISO Delay Time	t _{MID}	-	-	120	ns
MISO Setup Time	t _{MIS}	-	-	10	ns
MISO Hold Time	t _{MIH}	-	-	100	ns

 $^{^{\}star}$ Time values of CLK, MISO and MOSI are derived at the load capacitance of 10pF.

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6.8 User Test

This is a mode to monitor internal digital signal for design, development, manufacturing or shipping inspection. Set MODE1 pin to be "H" and/or the register: USER_TEST bit is "1" then TC32306FTG moves to User Test. In User Test, various internal signals for the adjustment are converted to analog and are output from DET_TMONI3 pin or DET_TMONI4 pin by the setting of register. The way of setting register of SPI Mode is different from that of EEPROM Mode.

Table 6-43 Inner Signal Monitor (DET_TMONI3 Pin)

Status	h'10[D3] USER_TEST MODE1Pin	h'15[D6] MONI3_SEL2	h'15[D5] MONI3_SEL1	h'15[D4] MONI3_SEL0	Signal	
Battery Saving	Х	Х	Х	Х	"Z"	
Run / Standby	0 and L	Х	Х	Х	"L" Output	
Run / Standby	1 or H	0	0	0	BRF_out	
Run / Standby	1 or H	0	0	1	BRF_in	
Run / Standby	1 or H	0	1	0	Data_compREF	
Run / Standby	1 or H	0	1	1	DRSSI_out	
Run / Standby	1 or H	1	0	0	Noise _out	
Run / Standby	1 or H	1	0	1	Peak_out	
Run / Standby	1 or H	1	1	0	"L" Output	
Run / Standby	1 or H	1	1	1	"L" Output	

X: Don't care

Table 6-44 Inner Signal Monitor (DET_TMONI4 Pin)

Status	h'10[D3] USER_TEST MODE1 Pin	h'15[D6] MONI3_SEL2	h'15[D5] MONI3_SEL1	h'15[D4] MONI3_SEL0	Signal	
Battery Saving	Х	Х	Х	Х	"Z"	
Run / Standby	0 and L	Х	Х	Х	"L" Output	
Run / Standby	1 or H	0	0	0	Data_compREF	
Run / Standby	1 or H	0	0	1	BRF_in	
Run / Standby	1 or H	0	1	0	BRF_out	
Run / Standby	1 or H	0	1	1	DRSSI_out	
Run / Standby	1 or H	1	0	0	Noise _out	
Run / Standby	1 or H	1	0	1	Peak_out	
Run / Standby	1 or H	1	1	0	"L" Output	
Run / Standby	1 or H	1	1	1	"L" Output	

X: Don't care

Table 6-45 Internal Signals Available in User Test

Signal	Explanation of Signal
BRF_out	Output of Bit Rate Filter
BRF_in	Input of Bit Rate Filter (FSK / ASK Demodulation LPF Output)
Data_compREF	Output of Data Comparator Reference Voltage
DRSSI_out	RSSI Output (Digital RSSI Output Converted to Analog)
Noise _out	Noise Detection Voltage Output of Noise Detector
Peak_out	Peak Hold Voltage Output of Peak Hold Circuit

-Use User Test only for development or evaluation, not for actual use (consumer products). Sensitivity of this IC may be worse by unexpected noise from monitor pins.

(1) Register settings in SPI Mode

In SPI User Test Mode, set them as same as normal SPI Mode.

(2) Register settings in EEPROM Mode

In EEPROM User Test Mode, the register can be set by SPI with connecting EEPROM. In EEPROM Mode, TC32306FTG as a master reads the register data in EEPROM through SPI lines. But in EEPROM User Test Mode, this IC as a slave accepts input from SPI lines. In the case, instructions in SPI format are different from those of SPI Mode. (The MBS "17" in the instruction is changed from 0 to 1.)

Table 6-46 Type of EEPROM Instructions in User Test and Settings

EE	PROM Control	17	16	15	14	13	12	l1	10
Single Read/Write	Write	1	0	0	0	х	1	1	0
Single Read/White	Read	1	0	0	0	х	1	1	1
	Write		0	0	0	Х	0	1	0
Burst Read/Write	Read	1	0	0	0	Х	0	1	1
	Confirmation of written data	1	0	0	0	Х	1	0	1
SP	I Function Stop	Except above data							

^{*} x: 0 or 1

Notice:

- -In User Test, must not set MODE2 pin to "L" (= for SPI Mode) to avoid output collision between TC32306FTG and EEPROM.
- -Take care of chattering to enter User Test by MODE1 pin.

6.9 Status Transition

The Status Transition is carried out after the register value is written. The status after the transition depends on the register settings. Each status can be moved as following figure by the register settings.

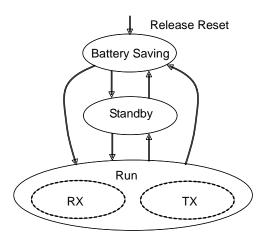


Fig 6-28 Status and Status Transition

^{*} SPI Function Stop: After writing SPI instruction data, subsequent data input will be disabled. Again, to enable the input data, enter SPI instruction data correctly after CS pin is set to be "H" once.

Table 6	2.47	Status	Control	in	CDI	Modo
Table (0-4/	Status	Control	ın	SPI	Mode

External Pin	Register	Settings	С	perations of Function Blo	cks	<u> </u>	
ENB Pin (Only in SPI Mode)	h'0A[D7] ENB	h'0A[D6] ACT	SPI	Reference Clock / Internal Regulator	Others	Status	
L	Х	Х	ON	OFF	OFF	Dotton Coving	
Н	0	Х	ON	OFF	OFF	Battery Saving	
Н	1	0	ON	ON	OFF	Standby	
Н	1	1	ON	ON	ON	Run	

X: Don't care

6.9.1 Power On → Battery Saving → Run

TC32306FTG will enter the setup sequence after Power On, releasing reset and register settings. In the setup sequence, this IC starts to setup and operate internal function blocks simultaneously.

- Delay Setting

The setup sequence will start after about $105.5~\mu s$ (Initial value) from the output level of Reference Clock Oscillator is over a certain level. Delay is selected by the register setting. Set it with considering Reference Clock oscillation stabilization time. The start timing of Delay is whichever later that output level of Reference Clock oscillator will be over a certain level or that TC32306FTG status will move to Run by the register settings.

Table 6-48 Delay Time Setting of the Setup Sequence Start

h'0D[D7] Delay_en	h'0D[D6] Delay2	h'0D[D5] Delay1	h'0D[D4] Delay0	Delay time until the setup sequence starts.
0	Х	Х	Х	105.5μs
1	0	0	0	105.5μs
1	0	0	1	211.1μs
1	0	1	0	316.5μs
1	0	1	1	527.5μs
1	1	0	0	949.5μs
1	I	Except Above	9	105.5μs

X: Don't care

Notice:

- Delay is derived from 30.32MHz Reference Clock Frequency.
- In SPI Mode, the initial register setting is h'0D[D7]Delay_en = "0". Delay is always about 105.5 μs.
- In SPI Mode, to enter the setup sequence with setting Delay time, move TC32306FTG status from Battery Saving/Standby to Run after the register setting.
- If the register of Delay time is set in Run status, the value of Delay time is valid at the next status moving form Battery Saving/Standby to Run.
- In EEPROM Mode (Except User Test), this IC enters the setup sequence with the setting Delay time because this IC status moves from Standby to Run after the register setting.
- Beware the relationship between supply voltage and reset, when to utilize the power on reset during boot sequence. (See the notice in 6.3.1)
- Example of Boot Sequence 1: RX (in SPI Mode)

The following Fig 6-29 shows status transition from Battery Saving/Standby to RX-Run.

- 1. Power On, then reset is released after the voltage supply becomes stable.
- 2. Set registers if necessary with Standby (ENB pin = "H", register:h'0A[D7]ENB = "1", register:h'0A[D6]ACT = "0"). Then internal regulators and Reference Clock Oscillator start to operate.
- 3. After the registers settings, set register:h'0A and move to Run. (ENB pin = "H", register:h'0A[D7]ENB = "1", register:h'0A[D6]ACT = "1")

- 4. The setup sequence and operation of internal function blocks will start after setting Delay time from the output level of Reference Clock Oscillator is over a certain level.
- 5. Signal Detections (RSSI & Noise Detection) with operating cycle (Initial value: 1.35 ms) set by register will start after the internal setup (about 0.22 ms) is finished.
- 6. Start timing of the demodulation output (from DATA_IO pin) is varied with Bit Rate Filter setting, data rate or other register settings. Preamble Detection output starts after the demodulation output is obtained.

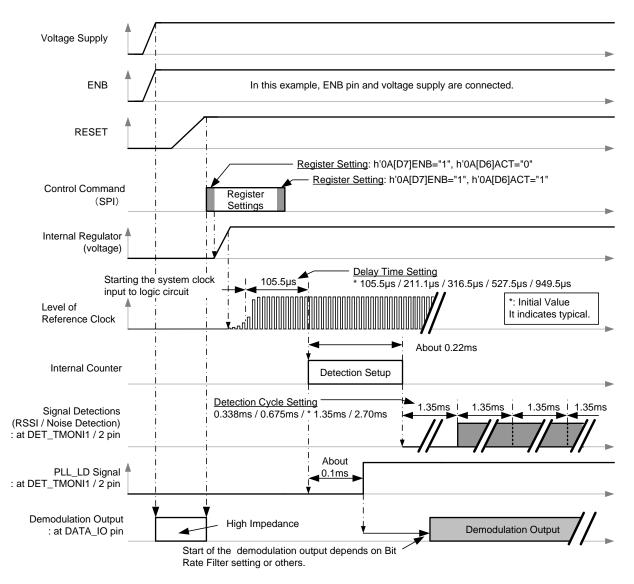


Fig 6-29 Example of Boot Sequence Timing Chart (SPI Mode / RX)

- To shorten the boot sequence of this IC, there is other way to be able to moving to Run without going through Standby. In this method, firstly set ENB pin = "H", h'0A [D7] ENB = "1" and h'0A [D6] ACT = "1", then set other registers. But in this way, if the internal setup and the register setting are overlapped each other, unexpected operation may occur. To avoid above, make the SPI speed too fast enough to communicate, or select the previous way as in Fig 6-29.
- Check the relationship between supply voltage and reset, when to utilize the power on reset during boot sequence. (See the notice in 6.3.1)

The following Fig 6-30 shows status transition from Battery Saving/Standby to TX-Run.

^{*} The example of timing chart may be omitted or simplified for explanatory purposes.

⁻ Example of Boot Sequence 2: TX (in SPI Mode)

- 1. Power On, and reset is released after the voltage supply becomes stable.
- 2. Set registers if necessary with Standby (ENB pin = "H", register:h'0A[D7]ENB = "1", register:h'0A[D6]ACT = "0"). Then internal regulators and Reference Clock Oscillator start to operate.
- 3. After the registers settings, set register:h'0A and move to Run. (ENB pin = "H", register:h'0A[D7]ENB = "1", register:h'0A[D6]ACT = "1")
- 4. The setup sequence and operation of internal function blocks will start after setting Delay time from the output level of Reference Clock Oscillator is over a certain level.
- 5. PLL Block will start after the internal setup (about 0.05 ms). After locking the expected frequency is detected, PLL_LD signal and Internal LD Signal will be from "L" to "H". PLL lock-up time is approximately 0.05 ms after internal setup is finished. About Internal LD Signal, see section 6.6.5.
- 6. Input the signal for modulation to DATA_IO pin. The RF modulated Signal will be transmitted from PA after PLL_LD signal turns to be "H" immediately, because initial value of register:h'13[D1]PA_en is "1". It is also possible to set the register:h'13[D1]PA_en = "0" at the first register setting.

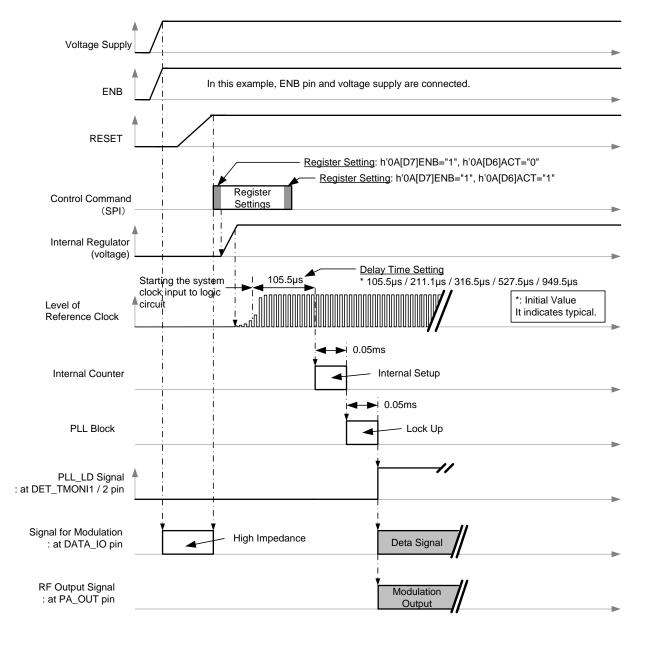


Fig 6-30 Example of Boot Sequence Timing Chart (SPI Mode / TX)

^{*} The example of timing chart may be omitted or simplified for explanatory purposes.

- To shorten the boot sequence of this IC, there is other way to be able to moving to Run without going through Standby. In this method, firstly set ENB pin = "H", h'0A [D7] ENB = "1" and h'0A [D6] ACT = "1", then set other registers. But in this way, if the internal setup and the register setting are overlapped each other, unexpected operation may occur. To avoid above, make the SPI speed too fast enough to communicate, or select the previous way as in Fig 6-30.
- In TX duration DATA_IO pin accepts data input, but that data is not transmitted when status of PA is Disable. Input data is invalid before PA enabling.
- Check the relationship between supply voltage and reset, when to utilize the power on reset during boot sequence. (See the notice in 6.3.1)
- Example of Boot Sequence 3: RX (in EEPROM Mode)

The following Fig 6-31 shows boot sequence of RX in EEPROM Mode.

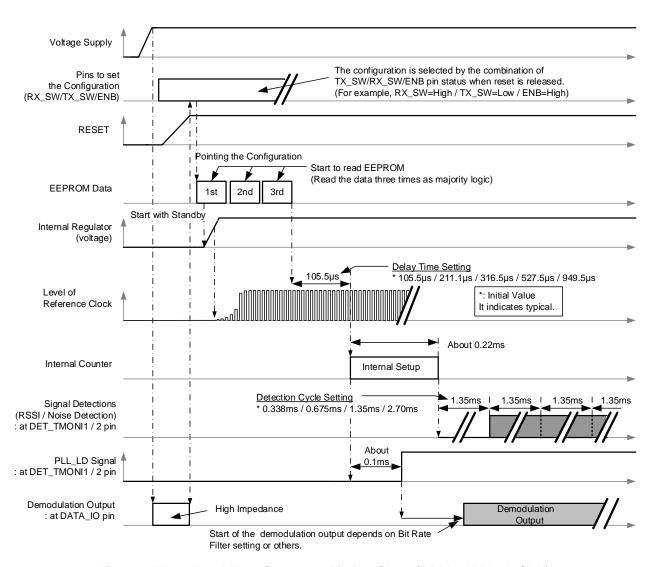


Fig 6-31 Example of Boot Sequence Timing Chart (EEPROM Mode / RX)

- * The example of timing chart may be omitted or simplified for explanatory purposes.
- 1. Power On, and reset is released after the voltage supply becomes stable.
- 2. Start to read the register of first set data area of EEPROM sequentially. (It is indicated by the combination of TX_SW pin, RX_SW pin and ENB pin.)
- 3. Start to operate with Standby despite of the value of the register: h'0A[D6]ACT. Internal regulators and Reference Clock Oscillator start to operate.
- 4. Read the second and third set data area continuously then the register setting is fixed.
- 5. Continue to operate depending on the setting of the register: h'0A[D6]ACT.

- From either slower timing which after reading the third register setup, or after the output level of Reference Clock Oscillator is over a certain level, the setup sequence and operation of internal function blocks will start after setting Delay time.
- 7. Signal Detections (RSSI & Noise Detection) with operating cycle (Initial value: 1.35 ms) set by register will start after the internal setup (about 0.22 ms) is finished.
- 8. Start timing of the demodulation output (from DATA_IO pin) is varied with Bit Rate Filter setting, data rate or other register settings. Preamble Detection output starts after the demodulation output is obtained.

- Set the configuration during the stable voltage supply.
- Check the relationship between supply voltage and reset, when to utilize the power on reset during boot sequence. (See the notice in 6.3.1)

6.9.2 Transition in Run Status (RX \rightarrow TX \rightarrow RX)

Transition of RX/TX each other in Run Status by setting the register: h'0A[D5]RX_TX.

Example: $RX \rightarrow TX \rightarrow RX$ (SPI Mode)

The example of the transition "RX \rightarrow TX \rightarrow RX" in SPI Mode is shown as Fig 6-32.

- 1. At the end of RX, set the register: h'0A[D5]RX_TX = "1" then TC32306FTG changes to TX.
- 2. After finishing all register settings for TX and CS pin is set to "H", this IC starts the setup sequence and PLL lock-up, then this IC is operated with setting registers.
- 3. At the end of TX, set the register: h'0A[D5]RX_TX = "0" then this IC changes to RX. After finishing all register settings for RX and CS pin is set to "H", this IC starts the setup sequence and PLL lock-up, then this IC is operated with setting registers.

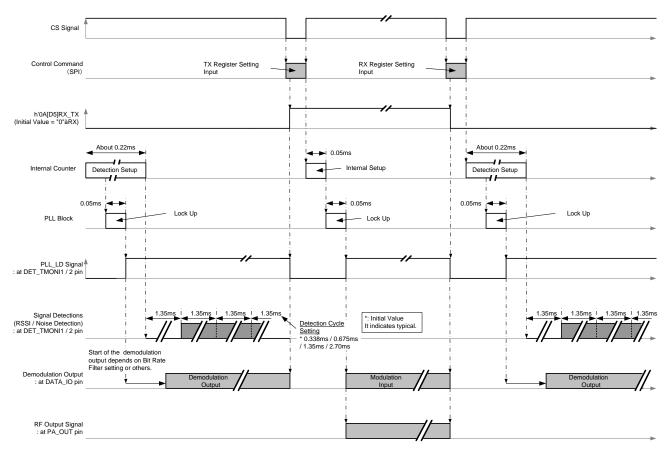


Fig 6-32 Example of Timing Chart (RX → TX → RX in SPI Mode)

- In transition between TX and RX through Battery Saving Status, it takes more time to start the next operation because of stopping the oscillation of XOSC.

Run → Battery Saving 6.9.3

TC32306FTG will move to Battery Saving by the setting of registers (h'0A[D7]ENB, h'0A[D6]ACT), ENB pin or RESET pin. In RX, it is possible to move to Battery Saving by the use of AutoOff function.

Notice:

In TX, to move to Battery Saving under disabled PA is recommended. In order to reduce unexpected signal transmission caused by the OFF timing gaps of each function blocks.

AutoOff Function 6.9.4

It is the function to move from Run (RX) to Battery Saving automatically without the register setting. AutoOff functions are the type A and B. These are valid when Signal Detections are enabled.

Notice:

- When to move to Battery Saving by AutoOff function, the value of registers (h'0A[D7]ENB, h'0A[D6]ACT) will not change. Output and check Status_MONI signal at DET_TMONI1 pin and/or DET TMONI2 pin to confirm the transition to Battery Saving by this function.
- About the pins behavior at the transition to Battery Saving by AutoOff, see Table 5-2.

Status	AutoOff	AutoOff	h'10[D4]	h'10[D5]
	Type B	Type A	AutoOffB_en	AutoOffA_en
-	OFF	OFF	0	0

Table 6-49 AutoOff Function Settings and Status

AutoOffA_en	AutoOffB_en	Type A	Type B	Status
0	0	OFF	OFF	-
0	1	OFF	ON	Move to Battery Saving if the determination of "Signal Detection"(DET_out signal = "H") is not indicated within the timer period set by register:h'1D[D7:D0].
1	0	ON	OFF	Move to Battery Saving if the determination of "No Signal Detection" is indicated (Un_DET_out signal = "H").
1	1	ON	ON	Move to Battery Saving whichever earlier AutoOff Type A or Type B.

(1) AutoOff Type A (AutoOff by Signal Detections)

TC32306FTG will move from Run to Battery Saving if the determination of "No Signal Detection" is indicated (Un_DET_out signal = "H"). It is valid to set register:h'10[D5]AutoOffA_en = "1".

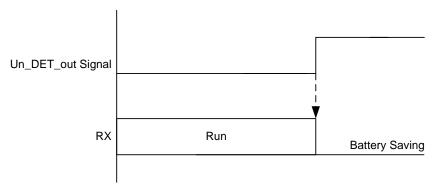


Fig 6-33 AutoOff Type A

^{*} The example of timing chart may be omitted or simplified for explanatory purposes.

- Continuing RX in AutoOff Type A

When AutoOff Type A is valid, TC32306FTG will keep to be RX despite of the condition of Un_DET_out signal and DET_out signal, once after DET_out signal turns to be "H" before Un_DET_out signal turns to be "H". To release from the continuing RX, need to set new register and/or change RESET/ENB pin.

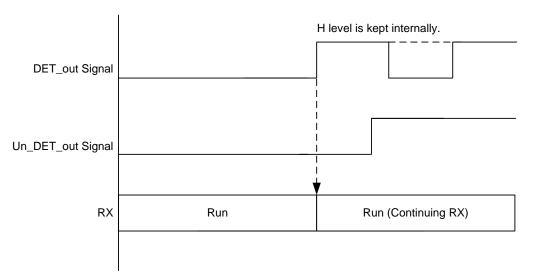


Fig 6-34 AutoOff Type A (Continuing RX)

Notice:

- The function of AutoOff Type A is valid immediately after the register: h'10 is finished to write.
- To use AutoOff Type A again from Battery Saving which status caused by the operation of AutoOff
 Type A, set TC32306FTG status to Battery Saving or Standby by setting new registers and/or
 change RESET/ENB pin.
- To use AutoOff Type A again in the continuing RX, set this IC status to Battery Saving or Standby by setting new registers and/or change RESET/ENB pin.

(2) AutoOff Type B (AutoOff by Timer Setting)

TC32306FTG will move from Run to Battery Saving if the determination of "Signal Detection" (DET_out signal = "H") is not indicated within the timer period set by register. It is valid to set register:h'10[D4]AutoOffB_en = "1". The duration of Run (RX timer period) is set by the register:h'1D[D7:D0]Ontime7..0.

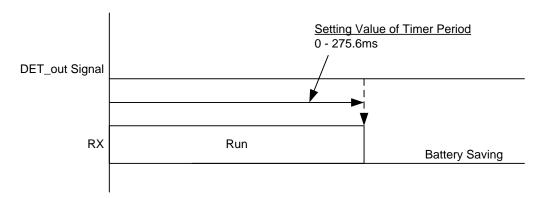


Fig 6-35 AutoOff Type B

^{*} The example of timing chart may be omitted or simplified for explanatory purposes.

^{*} The example of timing chart may be omitted or simplified for explanatory purposes.

- Continuing RX in AutoOff Type B

When AutoOff Type B is valid, TC32306FTG will stop the timer countdown and continue to be RX if DET_out signal turns to be "H" before the end of timer period set by register. After that, this IC keeps to be RX despite of the condition of DET_out signal. To move from continuing RX to Battery Saving, need to set new registers and/or change RESET/ENB pin.

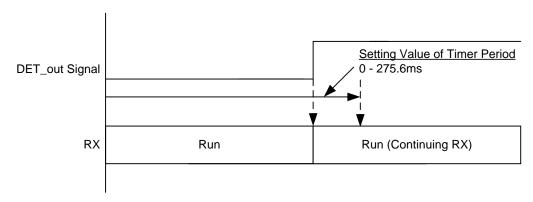


Fig 6-36 AutoOff Type B (Continuing RX)

Notice:

- The timer period setting is derived from 30.32MHz Reference Clock Frequency.
- The timer period setting is valid after TC32306FTG moves from Battery Saving or Standby to
- The timer countdown will start after about 0.06 ms from the start of internal setup, when this IC moves from Battery Saving or Standby to Run. The timer countdown will start immediately to finish register writing, if the setting of register:h'10 is valid in Run status.
- If the timer period is set to 0 ms, this IC will move to Battery Saving after the starting of timer countdown before RX.
- In the continuing RX, the stopping timer countdown of AutoOff Type B is not released even if register settings of RX operation are entered again. To use AutoOff Type B again, moving to Battery Saving or Standby is needed. In this case, the timer of AutoOff Type B is surely reset.
- In EEPROM Mode, the setting of the timer period is only 275.6 ms and cannot be set other value.

6.9.5 Change Settings during Run

The registers in Table 6-50 must have finished writing data before internal setup will start. When to change register settings after the internal setup has finished, do them in Battery Saving or Standby. About the internal setup, see section 6.9.1.

Table 6-50 Changing Register Prohibited during Run

Register	Location
Ntime10	h'1A [D7:D6]

The registers in Table 6-51 are valid by the transition from Battery Saving or Standby to Run. In SPI Mode, to be valid the register settings at the starting of TC32306FTG operation, set the registers during the status of Battery Saving or Standby then move to the status of Run.

Table 6-51 Register to be Valid by the Transition to Run

Register	Location
Delay20	h'0D[D6:D4]
Ontime70	h'1D[D7:D0]

^{*} The example of timing chart may be omitted or simplified for explanatory purposes.

6.10 Register Overview & Description

Available register's addresses in SPI Mode are "h'09-h'23", and these in EEPROM Mode are "h'0A-h'1C".

Table 6-52 Available Register Addresses

	Address					Type	Name	In EEPROM			
Code	AD7	AD6	AD5	AD4	AD3	AD2	AD1	AD0	туре	ivanie	Mode
h'09	0	0	0	0	1	0	0	1	R/W	Software Reset	-
h'0A	0	0	0	0	1	0	1	0	R/W	General Settings	0
h'0B	0	0	0	0	1	0	1	1	R/W	Local Frequency Settings 1	0
h'0C	0	0	0	0	1	1	0	0	R/W	Local Frequency Settings 2	0
h'0D	0	0	0	0	1	1	0	1	R/W	Delay & Drive Settings	0
h'0E	0	0	0	0	1	1	1	0	R/W	LNA, IF Filter, BRF Settings	0
h'0F	0	0	0	0	1	1	1	1	R/W	RX Function Settings 1	0
h'10	0	0	0	1	0	0	0	0	R/W	RX Function Settings 2	0
h'11	0	0	0	1	0	0	0	1	R/W	Charge2 Threshold Setting	0
h'12	0	0	0	1	0	0	1	0	R/W	TX Deviation Setting	0
h'13	0	0	0	1	0	0	1	1	R/W	TX PA Settings	0
h'14	0	0	0	1	0	1	0	0	R/W	Monitor Settings1	0
h'15	0	0	0	1	0	1	0	1	R/W	Monitor Settings2	0
h'16	0	0	0	1	0	1	1	0	R/W	RSSI Threshold Setting	0
h'17	0	0	0	1	0	1	1	1	R/W	Preamble Detector Setting 1	0
h'18	0	0	0	1	1	0	0	0	R/W	Preamble Detector Settings 2	0
h'19	0	0	0	1	1	0	0	1	R/W	Noise Detector Threshold Setting	0
h'1A	0	0	0	1	1	0	1	0	R/W	Signal Detector Settings	0
h'1B	0	0	0	1	1	0	1	1	R/W	Comparator Settings	0
h'1C	0	0	0	1	1	1	0	0	R/W	Peak Hold Settings	0
h'1D	0	0	0	1	1	1	0	1	R/W	AutoOff Type B Setting	-
h'1E	0	0	0	1	1	1	1	0	R	Signal Detect and Lock Detect Monitors	-
h'1F	0	0	0	1	1	1	1	1	R	Peak Hold Level Monitor	-
h'20	0	0	1	0	0	0	0	0	R	Data Comparator Monitor 1	-
h'21	0	0	1	0	0	0	0	1	R	Data Comparator Monitor 2	-
h'22	0	0	1	0	0	0	1	0	R	RSSI Level Monitor	-
h'23	0	0	1	0	0	0	1	1	R	Noise Signal Level Monitor	-

Notice:

- "o": accessible register's addresses in EEPROM Mode
- R / W: Read and Write Register
- R: Read only Register

Table 6-53 View of Register Settings (Reset & Status Control)

		Regis	Address				
Software Reset					h'09[D7:D0]		
Reset	-		-				
	(Output Current Drive	Settin	g	h'0D[D3:D1]		
	5	Status Control 1			h'0A[D7]		
Reset is		Buttery Saving	-		-		
Released			Sta	atus Control 2	h'0A[D6]		
		Run / Standby		Standby	-		
				Run	→ See next table		

Notice:

^{- &}quot;h'09" shows register's byte is "09" by hexadecimal, and [D7:D0] shows bit number are from the 7th- to the 0.

Table 6-54 View of Register Settings (In Run Status)

	ı	Register Settings	Address		
Antenna Switch Cor	ntrol		h'0A[D3:D2]		
Monitors		h'14[D6:D4], h'14[D2:D0]			
Except DET_out Signal	-		-		
DET_out Signal	DET_out Sig	gnal Output Control	h'10[D2]		
User Test			h'10[D3]		
Normal	-		-		
User Test	Monitor Sigr	nal Output	h'15[D6:D4], h'15[D2:D0]		
Delay Setting Enable	e / Disable		h'0D[D7]		
Disable	-		-		
Enable	Delay Time		h'0D[D6:D4]		
RF Frequency Band			h'0A[D1:D0]		
Local Frequency			h'0B[D7:D0], h'0C[D7:D0]		
RX & TX			h'0A[D5]		
	LNA Gain		h'0E[D7:D6]		
	IF Filter Ban	dwidth	h'0E[D5]		
	Demodulation	on	→ See next table		
	Bit Rate Filte	er Cutoff Frequency	h'0E[D4:D1]		
	Data Compa	arator Reference Voltage Charge Coefficient	h'1B[D5:D3]		
	Data Compa	arator Quick Charge 1 Enable / Disable	h'10[D7]		
	Data Compa	arator Quick Charge 2 Enable / Disable	h'10[D6]		
RX	Disable	-	-		
	Facilia	Quick Charge Coefficient	h'1B[D7:D6]		
	Enable	Quick Charge 2 Threshold Level	h'11[D7:D0]		
	DATA_IO C	ontrol	h'0F[D3]		
	AutoOff Typ	e A Enable / Disable	h'10[D5]		
		e B Enable / Disable	h'10[D4]		
	Disable	-	-		
	Enable	Duration	h'1D[D7:D0]		
	PA Control	•	h'13[D1]		
	Disable	-	-		
		Modulation	h'0A[D4]		
TX		FSK Deviation	h'12[D7:D2]		
	Enable	ASK -	-		
		Output Level (Coarse)	h'13[D3:D2]		
		Output Level (Fine)	h'13[D7:D4]		

Table 6-55 View of Register Settings (Detections Overall)

		Register Settings	Address		
emodul	ation (FSK / AS	SK)	h'0A[D4]		
	NIR (Near Int	erference Rejection) Filter Enable / Disable	h'10[D1]		
	Disable	-	-		
		NIR Filter Frequency Control	h'1B[D2:D1]		
	Enable	Threshold Level of Detection	h'0D[D0], h'0F[D0], h'12[D1:D0], h'13[D0 h'1A[D0], h'1B[D0], h'1C[D2:D0]		
	IF Detection		h'10[D0]		
		High Frequency Detector Enable / Disable	h'0F[D4]		
	Delay Detection	Disable -	-		
	Beteotion	Enable High Frequency Detector AutoOff	h'1A[D1]		
	Pulse Cou	nt Detection	-		
	Noise Detecti	on Enable / Disable	h'0F[D5]		
	Disable	Noise Addition by High Frequency Detector	h'19[D0]		
FSK		Threshold Level of Detection	h'19[D7:D2]		
	Enable	Detection Interval	h'1A[D7:D6]		
		Noise Addition by High Frequency Detector	h'19[D0]		
	RSSI Detection	on Enable / Disable	h'0F[D7]		
	Disable	-	-		
		Threshold Level of Detection	h'16[D7:D0]		
	Enable	Detection Interval	h'1A[D7:D6]		
	Preamble De	tection Enable / Disable	h'0F[D6]		
	Disable	-	-		
		Preamble Signal Cycle	h'17[D7:D0], h'18[D7]		
		Error Margin	h'18[D6:D0]		
	Enable	Number of Times for Judgment	h'1A[D4:D3]		
		Detection Trigger	h'1A[D2]		
	Data Compar	ator Quick Charge 2 Enable / Disable	h'10[D6]		
	Disable	-	-		
		Limiter (Peak Hold Voltage Discharge Coefficient)	h'1C[D7:D5]		
	Enable	Limiter (Peak Hold Voltage Charge Coefficient)	h'1C[D4:D3]		
	RSSI Detection	on Enable / Disable	h'0F[D7]		
	Disable	-	-		
4.014		Threshold Level of Detection	h'16[D7:D0]		
ASK	Enable	Detection Interval	h'1A[D7:D6]		
	Preamble De	tection Enable / Disable	h'0F[D6]		
	Disable	-	-		
		Threshold Level of Detection	h'17[D7:D0], h'18[D7]		
		Number of Times for Judgment	h'18[D6:D0]		
	Enable	Detection Interval	h'1A[D4:D3]		
		Detection Trigger	h'1A[D2]		

6.10.1 h'09 Software Reset

Table 6-56 Register (h'09)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	RESET7	RESET6	RESET5	RESET4	RESET3	RESET2	RESET1	RESET0
Initial	0	0	0	0	0	0	0	0
Туре	R/W							

- Set register:[D7:D0] = b'01010101: Initialize Register
- Others: Not Initialize

TOSHIBA

After entering register:[D0] data, TC32306FTG becomes Reset status, and then the reset is released whichever faster the rising edge of next SPI-Clock signal or the rising edge of next SPI-CS signal. Set this IC to SPI Read, this IC outputs register's data "b'00000000". Set this IC to SPI Confirmation Write, then this IC outputs registers' data written just before.

6.10.2 h'0A General Settings

Table 6-57 Register (h'0A)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	ENB	ACT	RX_TX	FSK_ASK	TX_SW	RX_SW	BAND1	BAND0
Initial	0	1	0	0	0	0	0	0
Type	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

[D7]ENB [Status Control 1]

The combinations of this register and register:[D6] result as the right table.

In SPI Mode, ENB pin = "H" leads these settings are valid and ENB pin = "L" leads TC32306FTG is Battery Saving Status.

The combinations of this register and register:[D7] result as the right table.

In SPI Mode, ENB pin = "H" leads these settings are valid and ENB pin = "L" leads TC32306FTG is Battery Saving Status.

[D7]ENB	[D6]ACT	Status
0	Х	Battery Saving
1	0	Standby
1	1	Run

X: Don't care

[D5]RX_TX [RX / TX]

0: Receiving / 1: Transmitting

[D4]FSK_ASK [Modulation & Demodulation]

0: FSK / 1: ASK

[D3]TX_SW [Antenna Switch Control (TX)]

0: TX_SW pin = "L" / 1: TX_SW pin = "H"

In SPI Mode, this register result as the right table.

In EEPROM Mode, these settings are invalid.

[D2]RX_SW [Antenna Switch Control (RX)]

0: RX_SW pin = "L" / 1: RX_SW pin = "H"

In SPI Mode, this register result as the right table.

In EEPROM Mode, these settings are invalid.

[D3]TX_SW [D2]RX_SW	Status	TX_SW Pin RX_SW Pin
Х	Except Run / Standby	L
0	Run / Standby	L
1	Run / Standby	Н

X: Don't care

L: Pull Down

[D1:D0]BAND1..0 [RF Frequency Band]

[D1:D0] = b'00: 315 MHz

[D1:D0] = b'01: 434 MHz

[D1:D0] = b'10: 868 / 915 MHz

[D1:D0] = b'11: 868 / 915 MHz

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6.10.3 h'0B VCO Frequency Settings 1

Table 6-58 Register (h'0B)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	NC3	NC2	NC1	NC0	FC11	FC10	FC9	FC8
Initial	1	0	0	1	0	0	1	1
Туре	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

[D7:D4]NC3..0 [Local Frequency: Integer Counter]

 $NC = 2^3 \times NC3 + 2^2 \times NC2 + 2^1 \times NC1 + 2^0 \times NC0$

Initial Value: NC = 9

h'0C [D7:D0]FC7..0 & h'0B [D3:D0]FC11..8 [Local Frequency: Fractional Counter]

 $FC = -2^{11}xFC11 + 2^{10}xFC10 + 2^{9}xFC9 + 2^{8}xFC8 + 2^{7}xFC7 + 2^{6}xFC6 + 2^{5}xFC5 + 2^{4}xFC4 + 2^{3}xFC3 + 2^{2}xFC2 + 2^{1}xFC1 + 2^{0}xFC0$

Initial Value: FC = 1016 (Two's complement format) Must set the FC value between -1516 to +1515.

Example1)

VCO frequency "fvco" is set as follows.

fvco = (NC+53) x fosc + FC x fstep

fvco: VCO Frequency

fosc: Reference Clock Frequency (30.32MHz)

fstep: Frequency Step (= fosc / 3032)

<Case of setting fvco = 1890MHz>

fvco = 1890MHz / fosc = 30.32MHz / fstep = 10kHz (= 3032 / 30.32MHz)

NC = fvco / fosc - 53 = 1890MHz / 30.32MHz - $53 = 9.335 \rightarrow NC = 9$ (This number is rounded to an integer.)

FC = (fvco / fosc - (NC+53)) x fosc / fstep = (1890MHz / 30.32MHz - (9+53)) x 30.32MHz / 10kHz = 1016

NC = 9 → NC = "b'1001" (Binary)

FC = 1016 → FC = "b'001111111000" (Two's complement format)

Example2)

RX frequency "frx" and TX frequency "ftx" are set as follows.

 $frx = (fvco / nd) - f_if = [(NC+53) \times fosc + FC \times fstep] / nd - f_if$

ftx = fvco/ nd = [(NC+53) x fosc + FC x fstep] / nd

frx: RX frequency

ftx: TX frequency

f_if: IF frequency (230 or 280 kHz)

nd: Division Ratio (nd = 6 at 315MHz Band, nd = 4 at 434MHz Band, nd = 2 at 868 / 915MHz Band)

<Case of setting frx = 314.94MHz>

 $frx = 314.94MHz / fosc = 30.32MHz / fstep = 10kHz (= 3032 / 30.32MHz) / f_if = 280kHz$

In this case, nd = 6, as frequency band is 315MHz.

Actually to calculate frx, firstly calculate fvco based on frx, next determine the number of NC and FC.

 $fvco = (frx - f_if) x nd = (314.94MHz - 0.28MHz) x 6 = 1887.96MHz$

NC = fvco / fosc - 53 = 1887.96MHz / 30.32MHz - 53 = 9.268 \rightarrow NC=9 (This number is rounded to an integer.)

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FC = (fvco / fosc - (NC+53)) x fosc / fstep = (1887.96MHz / 30.32MHz - (9 + 53)) x 30.32MHz / 10kHz = 812

 $NC = 9 \rightarrow NC = "b'1001"$ (Binary)

FC = 812 → FC ="b'00110010110" (Two's complement format)

By using those NC and FC, fvco and frx can be calculated again.

fvco = (NC+53) x fosc + FC x fstep = (9 + 53) x 30.32MHz + 812 x 10kHz = 1887.96MHz

 $frx = (fvco / nd) + f_if = (1887.96MHz / 6) + 280kHz = 314.94MHz$

<Case of setting ftx = 433.92MHz>

ftx = 433.92MHz / fosc = 30.32MHz / fstep = 10kHz (= 3032 / 30.32MHz)

In this case, nd = 4, as frequency band is 433MHz, and the result of calculations aren't affected by f_if.

Similar to the case of frx, firstly calculate fvco based on ftx, next determine the number of NC and FC.

fvco = ftx x nd = 433.92MHz x 6 = 1732.68MHz

 $NC = fvco / fosc - 53 = 1735.68MHz / 30.32MHz - 53 = 4.245 \rightarrow NC=4$ (This number is rounded to an integer.)

FC = (fvco / fosc - (NC+53)) x fosc / fstep = (1735.68MHz / 30.32MHz - (4 + 53)) x 30.32MHz / 10kHz = 744

 $NC = 4 \rightarrow NC = "b'0100"$ (Binary)

FC = 744→ FC ="b'00101110100" (Two's complement format)

By using those NC and FC, fvco and ftx can be calculated again.

fvco = (NC+53) x fosc + FC x fstep = (4 + 53) x 30.32MHz + 744 x 10kHz = 1735.68MHz

ftx = fvco / nd = 1735.68MHz / 4 = 433.92MHz

Notice: The change of "fosc" results the change of "fvco" in the same NC and FC.

6.10.4 h'0C VCO Frequency Settings 2

Table 6-59 Register (h'0C)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	FC7	FC6	FC5	FC4	FC3	FC2	FC1	FC0
Initial	1	1	1	1	1	0	0	0
Туре	R/W							

[D7:D0]FC7..0 [Local Frequency: Fractional Counter]

See register h'0B section.

6.10.5 h'0D Delay & Drive Functions

Table 6-60 Register (h'0D)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	Delay_en	Delay2	Delay1	Delay0	DATA_IO_D	MISO_D	TMONI_D	NIR_H2
Initial	0	0	0	0	0	0	0	0
Туре	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

[D7]Delay_en [Delay Setting]

0: Disable fixed as 105.5μs

1: Enable set by [D6:D4]Delay_2..0

[D6:D4]delay_2..0 [Delay Time]

TC32306FTG status changes from Battery Saving / Standby to Run, then this IC starts operation with this delay time when the register:[D7]Delay_en value is "1".

[D6:D4] = b'000: Delay Time = $105.5 \mu s$

 $[D6:D4] = b'001: Delay Time = 211.1 \mu s$

 $[D6:D4] = b'010: Delay Time = 316.5 \mu s$

[D6:D4] = b'011: Delay Time = $527.5\mu s$

[D6:D4] = b'100: Delay Time = $949.5\mu s$

Other: Delay Time = $105.5\mu s$

Notice:

To start TC32306FTG with this delay time, changing the status from Battery Saving / Standby to Run after setting this register. If this register is set during Run, this register setting will be valid after the next transition from Battery Saving / Standby to Run.

[D3]DATA_IO_D [DATA_IO Output Drive Setting]

0: Low / 1:High

[D2]MISO_D [MISO Output Drive Setting]

0: Low / 1:High

[D1]TMONI_D [DET_TMONI1 / DET_TMONI2 Output Drive Setting]

0: Low / 1:High

[D0] NIR_H2

When to use NIR filter (h'10[D1]NIR_Fil_en = "1"), set this register "0".

6.10.6 h'0E LNA, IF Filter, BRF Settings

Table 6-61 Register (h'0E)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	Lna_gain1	Lna_gain0	IFBW	BRF_Bit3	BRF_Bit2	BRF_Bit1	BRF_Bit0	-
Initial	0	0	0	1	0	0	1	0
Type	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

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[D7:D6]Lna_gain1..0 [LNA Gain]

LNA gain depends on RF frequency band.

[D7:D6] = b'00: LNA Gain = Minimum Setting

[D7:D6] = b'11: LNA Gain = Maximum Setting



[D5]IFBW [IF Filter Bandwidth]

[D5]IFBW	IF Filter Bandwidth	IF Frequency
0	320kHz	230kHz
1	270kHz	280kHz

Change IF Frequency depends on IF Filter Bandwidth.

[D4:D1]BRF_Bit3..0 [Bit Rate Filter Cutoff Frequency]

For details, see Table 6-25.

[D0]

Set to "0" surely.

6.10.7 h'0F RX Function Settings 1

Table 6-62 Register (h'0F)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	Drssi_en	Preamble_ en	Ndet_en	Hdet_en	Dataout_ cnt_en	Digital_en	Det_reset_n	NIR_L2
Initial	0	0	0	0	0	1	1	1
Туре	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

[D7]Drssi_en [RSSI Detection]

0: Disable / 1: Enable

[D6]Preamble_en [Preamble Detection]

0: Disable / 1: Enable

[D5]Ndet_en [Noise Detection]

0: Disable / 1: Enable

[D4] Hdet_en [High Frequency Detector]

In Delay Detection ($h'10[D0]Sel_Det = "0"$), this register setting is valid.

0: Disable / 1: Enable

[D3]Dataout_cnt_en [DATA_IO Control]

0: Disable / 1: Enable

[D2]Digital_en [Digital Block Control]

Digital Block (Detctor, LPF(ASK), LPF(FSK), BRF, Data COMP) Control

0: Disable / 1: Enable

[D1]Det_reset_n [Detection Reset (RSSI Detection / Noise Detection / Preamble Detection)]

0: Detection Reset (Auto resume)

1: Reset is released

Notice:

These detections are reset after writing all the registers in this address.

The function is resumed automatically at the rising edge of CS signal after setting this register.

TC32306FTG always outputs previous input value of the register whichever the auto resume or not,

(If this register is written to "0", the register outputs "0", after that auto resume.)

[D0] NIR_L2

When to use NIR filter (h'10[D1]NIR_Fil_en = "1") and Delay Detection (h'10[D0]Sel_Det = "0"), set this register "1". When to use NIR filter (h'10[D1]NIR_Fil_en = "1") and Pulse Count Detection (h'10[D0]Sel_Det = "1"), set this register "0".

6.10.8 h'10 RX Function Settings 2

Table 6-63 Register (h'10)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	Charge1_en	Charge2_en	AutoOffA_ en	AutoOffB_ en	USER_ TEST	DET_out_ cnt_en	NIR_Fil_en	Sel_Det
Initial	0	1	0	0	0	1	0	0
Туре	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

[D7]Charge1_en [Data Comparator Quick Charge 1]

0: Disable / 1: Enable

[D6]Charge2_en [Data Comparator Quick Charge 2]

0: Disable / 1: Enable

[D5]AutoOffA_en [AutoOff Type A]

0: Disable / 1: Enable

Notice: When to use the function of AutoOff Type A with using Preamble Detection, set both Data Comparator Quick Charge 1 and 2 to the status of ON.

[D4] AutoOffB_en [AutoOff Type B]

0: Disable / 1: Enable

[D3]USER_TEST [User Test]

0: Disable / 1: Enable (Internal monitor signals output from DET_TMONI3 / DET_TMONI4 Pin.)

[D2]Det_out_cnt_en [DET_out Signal Output Control]

0: Disable / 1: Enable

[D1]NIR_Fil_en [NIR (Near Interference Rejection) Filter Control]

When to use FSK Demodulation (h'0A[D4]FSK_ASK = "0"), this setting is valid.

0: Disable / 1: Enable

[D0] Sel_Det [IF Detection Select]

When to use FSK Demodulation (h'0A[D4]FSK_ASK = "0"), this setting is valid.

0: Delay Detection / 1: Pulse Count Detection



6.10.9 h'11 Charge2 Threshold Setting

Table 6-64 Register (h'11)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	Charge2_ Th7	Charge2_ Th6	Charge2_ Th5	Charge2_ Th4	Charge2_ Th3	Charge2_ Th2	Charge2_ Th1	Charge2_ Th0
Initial	0	0	1	1	1	1	0	1
Туре	R/W							

[D7:D0]Charge2_Th7..0 [Quick Charge 2 Threshold Level]

When to set Data Comparator Quick Charge 2 (h'10[D6]Charge2_en = "1") and FSK Demodulation (h'0A[D4]FSK_ASK = "0"), this setting is valid.

In ASK Demodulation (h'0A[D4]FSK_ASK = "1"), input to this register is invalid, because the threshold level is automatically set.

- Setting Range

[D7:D0] = 0 - 255 (b'00000000 - b'11111111)

Initial Value: 61 (b'00111101)

For details, see section 6.5.9.

Notice: In ASK Demodulation (h'0A[D4]FSK_ASK = "1"), the value of that threshold level for automatically setting cannot be read.

6.10.10 h'12 TX Deviation Setting

Table 6-65 Register (h'12)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	Dev5	Dev4	Dev3	Dev2	Dev1	Dev0	NIR_2H1	NIR_2H0
Initial	0	0	1	1	0	0	0	0
Туре	R/W	R/W						

[D7:D2]Dev5..0 [Deviation]

This deviation depends on the setting of RF frequency band.

- Setting Range

[D7:D2] = 0 - 63 (b'000000 - 111111)

Initial Value: 12 (b'001100)

- Deviation Setting Range at 30.32MHz Reference Clock Frequency.

315 MHz: Unmodulated, from +/-1.67kHz to +/-105kHz 434 MHz: Unmodulated, from +/-2.5kHz to +/-157.5kHz 868 / 915 MHz: Unmodulated, from +/-5kHz to +/-315kHz

Notice: When to set this register value to "0", RF output signal is unmodulated.

Example)

Deviation: $\pm - \text{dev} = \text{fd} \times \text{n} / \text{nd}$

fd: Frequency Resolution of VCO 10kHz (= fosc / 3032) * fosc: Reference Clock Frequency (30.32MHz) nd: Division Ratio (nd = 6 at 315MHz Band, nd = 4 at 434MHz Band nd = 2 at 868 / 915MHz Band)

n: value of register:[D7:D2]Dev5..0 (Converted to decimal)

Notice:

In ASK Receiving / Transmitting and FSK Receiving, settings of register h'12[D7:D2] are invalid.

The change of "fosc" results the change of deviation.

[D1] NIR_2H1

When to use NIR filter (h'10[D1]NIR_Fil_en = "1"), set this register "0".

[D0] NIR_2H0

When to use NIR filter (h'10[D1]NIR_Fil_en = "1") and Delay Detection (h'10[D0]Sel_Det = "0"), set as follows.

At intermittent RX: set this register "0". / At continuous RX: set this register "1".

When to use NIR filter (h'10[D1]NIR_Fil_en = "1") and Pulse Count Detection (h'10[D0]Sel_Det = "1"), set this register "0".

6.10.11h'13 TX PA Settings

Table 6-66 Register (h'13)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	TX_ subgain3	TX_ subgain2	TX_ subgain1	TX_ subgain0	TX_gain1	TX_gain0	PA_en	NIR_H1
Initial	1	1	1	1	1	1	1	0
Туре	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

[D7:D4] TX_subgain3..0 [Output Level (Fine)]

The output level depends on RF frequency band.

[D7:D4] = b'0000: Minimum [D7:D4] = b'1111: Maximum

[D3:D2] TX_gain1..0 [Output Level (Coarse)]

The output level depends on RF frequency band.

[D3:D2] = b'00: Minimum [D3:D2] = b'11: Maximum

Notice:

In ASK and FSK Receiving, settings of register h'13[D7:D2] are invalid.

[D1]PA_en [PA Enable / Disable]

The combination register:h'0A[D5]RX_TX and Internal LD Signal (The result of PLL lock detection: see below) results the operation of PA in the below table.

h'0A[D5] RX_TX	[D1]PA_en	Internal LD Signal	PA Function
0	Х	Х	Disable
1	Х	L	Disable
1	0	Х	Disable
1	1	Н	Enable

X: Don't care

Internal LD Signal is only use for PA, and the signal keeps "H" after the first rising edge of PLL_LD Signal. Above function is only available in TX and the Internal LD Signal cannot be monitored. To release the signal holding state, set one of the follows.

- Set TC32306FTG in the status of Battery Saving or Standby.
- Change from TX to RX.
- Change TX modulation. (ASK ↔ FSK)
- Change RF frequency. (In the change in the value of register "h'0B" and/or "h'0C")
- Change the value of register:h'12[D7:D2] for TX deviation. (This is only valid in FSK setting (h'0A[D4]FSK_ASK = "0"))

[D0] NIR_H1

When to use NIR filter (h'10[D1]NIR_Fil_en = "1"), set this register "0".



6.10.12 h'14 Monitor Settings1

Table 6-67 Register (h'14)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	-	MONI1_ SEL2	MONI1_ SEL1	MONI1_ SEL0	-	MONI2_ SEL2	MONI2_ SEL1	MONI2_ SEL0
Initial	0	0	0	0	0	0	0	0
Туре	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

[D7]

Set to "0" surely.

[D6:D4] MONI1_SEL2..0 [DET_TMONI1 Pin Output]

[D6] MONI1_SEL2	[D5] MONI1_SEL1	[D4] MONI1_SEL0	Signal Name	Description
0	0	0	-	Low level output
0	0	1	DET_out	The result of "Signal Detection"
0	1	0	Preamble_DET_ out	The result of Preamble detection
0	1	1	RSSI_DET_out	The result of RSSI detection
1	0	0	NDET_out	The result of Noise detection
1	0	1	Status_MONI	TC32306FTG status (Standby, Run) / Battery Saving
1	1	0	Un_DET_out	The result of "No Signal Detection"
1	1	1	PLL_LD	The result of PLL lock detection
1	1	1	PLL_LD	The result of PLL lock detection

[D3]

Set to "0" surely.

[D2:D0]MONI2_SEL2..0 [DET_TMONI2 Pin Output]

[D2] MONI2_SEL2	[D1] MONI2_SEL1	[D0] MONI2_SEL0	Signal Name	Description
0	0	0	-	Low level output
0	0	1	DET_out	The result of "Signal Detection"
0	1	0	Preamble_DET_ out	The result of Preamble detection
0	1	1	RSSI_DET_out	The result of RSSI detection
1	0	0	NDET_out	The result of Noise detection
1	0	1	Status_MONI	TC32306FTG status (Standby, Run) / Battery Saving
1	1	0	Un_DET_out	The result of "No Signal Detection"
1	1	1	PLL_LD	The result of PLL lock detection



6.10.13 h'15 Monitor Settings2

Table 6-68 Register (h'15)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	-	MONI3_ SEL2	MONI3_ SEL1	MONI3_ SEL0	-	MONI4_ SEL2	MONI4_ SEL1	MONI4_ SEL0
Initial	0	0	0	0	0	0	0	0
Туре	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

[D7]

Set to "0" surely.

[D6:D4]MONI3_SEL2..0 [DET_TMONI3 Pin Output]

When to select User Test (h'10[D3]USER_TEST = "1" and/or MODE1 pin = "H"), these settings are valid.

[D6] MONI3_SEL2	[D5] MONI3_SEL1	[D4] MONI3_SEL0	Signal Name	Description
0	0	0	BRF_out	Bit Rate Filter output signal
0	0	1	BRF_in	Bit Rate Filter input signal
0	1	0	Data_compREF	Data Comparator Reference voltage
0	1	1	DRSSI_out	RSSI output voltage (After the digital to analog conversion)
1	0	0	Noise _out	Noise detection output voltage
1	0	1	Peak_out	Peak hold voltage of Peak Hold Circuit
1	1	0	-	Low level output
1	1	1	-	Low level output

[D3]

Set to "0" surely.

[D2:D0]MONI4_SEL2..0 [DET_TMONI4 Pin Output]

When to select User Test (h'10[D3]USER_TEST = "1" and/or MODE1 pin = "H"), these settings are valid.

[D2] MONI4_SEL2	[D1] MONI4_SEL1	[D0] MONI4_SEL0	Signal Name	Description
0	0	0	Data_compREF	Data Comparator Reference voltage
0	0	1	BRF_in	Bit Rate Filter input signal
0	1	0	BRF_out	Bit Rate Filter output signal
0	1	1	DRSSI_out	RSSI output voltage (After the digital to analog conversion)
1	0	0	Noise _out	Noise detection output voltage
1	0	1	Peak_out	Peak hold voltage of Peak Hold Circuit
1	1	0	-	Low level output
1	1	1	-	Low level output



6.10.14 h'16 RSSI Threshold Setting

Table 6-69 Register (h'16)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	DRSSI_Th7	DRSSI_Th6	DRSSI_Th5	DRSSI_Th4	DRSSI_Th3	DRSSI_Th2	DRSSI_Th1	DRSSI_Th0
Initial	0	0	0	0	0	0	0	0
Туре	R/W							

[D7:D0]DRSSI_Th7..0 [RSSI Threshold Level of Detection]

- Setting Range

[D7:D0] = 0 - 255 (b'00000000 - b'11111111)

Initial Value: 0

To set RSSI threshold level of detection, refer the value of "h'22[D7:D0] RSSI Level Monitor".

6.10.15 h'17 Preamble Detector Setting 1

Table 6-70 Register (h'17)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	Pre_Time7	Pre_Time6	Pre_Time5	Pre_Time4	Pre_Time3	Pre_Time2	Pre_Time1	Pre_Time0
Initial	1	0	0	1	1	1	1	0
Туре	R/W							

h'18[D7] & h'17[D7:D0]Pre_Time8..0 [Preamble Signal Cycle]

When to set Preamble detection (h'0F[D6]Preamble_en = "1"), this setting is valid.

- Setting Range

h'18[D7] & h'17[D7:D0] = 0 - 511 (b'000000000 - b'1111111111)

Initial Value: 158(b'010011110)

See section 6.5.6 about the Function of Preamble detection.

Notice: The cutoff frequency of Bit Rate Filter is derived from 30.32MHz Reference Clock Frequency.

6.10.16 h'18 Preamble Detector Settings 2

Table 6-71 Register (h'18)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	Pre_Time8	Err_Margin6	Err_Margin5	Err_Margin4	Err_Margin3	Err_Margin2	Err_Margin1	Err_Margin0
Initial	0	0	0	0	0	1	0	1
Туре	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

[D7]Pre_Time8 [Preamble Signal Cycle]

See register h'17.



[D6:D0]Err_Margin6..0 [Error Margin]

When to set Preamble detection (h'0F[D6]Preamble_en = "1"), this setting is valid.

- Setting Range

[D6:D0] = 0 - 127 (b'0000000 - b'1111111)

Initial Value: 5 (b'0000101)

See section 6.5.6 about the Function of Preamble Detection.

Notice: The cutoff frequency of Bit Rate Filter is derived from 30.32MHz Reference Clock Frequency.

6.10.17 h'19 Noise Detector Threshold Setting

Table 6-72 Register (h'19)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	Ndet_Th5	Ndet_Th4	Ndet_Th3	Ndet_Th2	Ndet_Th1	Ndet_Th0	-	Add_Hdet_ en
Initial	0	0	0	0	0	0	0	0
Туре	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

[D7:D2] Ndet_Th5..0 [Noise Detector Threshold Level of Detection]

When to set FSK Demodulation (h'0A[D4]FSK_ASK = "0") and Noise Detection (h'0F[D5] Ndet_en = "1"), this setting is valid.

- Setting Range

[D7:D2] = 0 - 63 (b'000000 - b'111111)

Initial Value: 0

To set Noise Detector threshold level, refer the value of "h'23[D7:D0] Noise Signal Level Monitor".

[D1]

Set to "0" surely.

[D0] Add_Hdet_en [Noise Addition by High Frequency Detector]

0: Disable / 1: Enable

6.10.18 h'1A Signal Detector Settings

Table 6-73 Register (h'1A)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	Ntime1	Ntime0	-	Pre_ DetCount1	Pre_ DetCount0	Pre_DetTrig	Auto_Hdet_ Off	NIR_H0
Initial	1	0	0	1	0	0	0	0
Туре	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

[D7:D6]Ntime1..0 [Detection Interval]

Set the interval Noise Detection and RSSI Detection.

[D7]Ntime1	[D6]Ntime0	n	Judgment Interval (tdet)
0	0	1	0.338ms
0	1	2	0.675ms
1	0	4	1.35 ms
1	1	8	2.70ms

tdet: Detection Interval, fosc: Reference Clock Frequency (30.32MHz)

n: Coefficient determined by the setting of "[D7:D6]Ntime1..0"

 $tdet = n \times 1/((fosc / 256) / 40) sec$

Notice

This tdet value in above table is derived from 30.32MHz Reference Clock Frequency.

To be valid the setting of this register setting, finish writing the value to this register before the internal setup will start. When the internal setup has finished and TC32306FTG is Run status, move this IC status to Battery Saving / Standby and change this register value.

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[D5]

Set to "0" surely.

[D4:D3]Pre_DetCount1..0 [Preamble Detection Number of Times for Judgment]

- Judged "Detection" by continuous detection within the error margin.
- Judged "No Detection" by continuous detection outside the error margin.

[D2]Pre_DetTrig [Preamble Detection Trigger]

- 0: Judged by period (Checked at the rising edge of the signal)
- 1: Judged by bit (Checked both rising and falling edge of the signal)

Judgment Criteria	[D4] Pre_DetCount1	[D3] Pre_DetCount0	[D2] Pre_DetTrig	Number of Times for Judgment / Detection Interval
	0	0	0	3 Period
	0	0	1	6 Bit
	0	1	0	4 Period
Signal Detection	0	1	1	8 Bit
	1	0	0	5 Period (Initial)
	1	0	1	10 Bit
	1	1	0	6 Period
	1	1	1	12bit
No Signal Detection	Х	Х	0	3 Period (Initial)
	Х	Х	1	4 bit

X: Don't care

[D1] Auto_Hdet_Off [High Frequency Detector AutoOff]

When to set High Frequency Detection (h'0F[D4] Hdet_en = "1"), this setting is valid.

0: Disable / 1: Enable

[D0] NIR_H0

When to use NIR filter (h'10[D1]NIR_Fil_en = "1"), set this register "0".

6.10.19 h'1B Data Comparator Settings

Table 6-74 Register (h'1B)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	Charge2_ Ref1	Charge2_ Ref0	Cmp_Ref2	Cmp_Ref1	Cmp_Ref0	NIR_Frqth1	NIR_Frqth0	NIR_2L1
Initial	0	1	1	0	0	0	0	0
Туре	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W



[D7:D6]Charge2_Ref1..0 [Data Comparator Quick Charge Coefficient]

When to set Data Comparator Quick Charge 2 (h'10[D6]Charge2_en = "1"), this setting is valid. Set the tracking time constant T of the data comparator reference voltage (vref). This is valid only if an absolute value of the difference between vref and vi (Data comparator input voltage) will be greater than the threshold level set by register:h'11[D7:D0]Charge2_Th7..0".

tracking time constant τ : $\tau = nc' / fbc$

nc': Inverse of "(1/nr)+(1/nc)"

nc: Setting value of this register: Charge2_Ref1..0 (Refer to the table below.)

nr: Setting value of this register:[D5:D3]Cmp_Ref2..0

fbc: Internal clock signal frequency depends on Bit Rate Filter register:h'0E [D4:D1]BRF_Bit3..0

[D7]Charge2_Ref1	[D6]Charge2_Ref0	1/nc	nc
0	0	1/4	4
0	1	1/8	8
1	0	1/16	16
1	1	1/32	32

See section 6.5.9 about Data Comparator Quick Charge 2.

Notice: The cutoff frequency of Bit Rate Filter is derived from 30.32MHz Reference Clock Frequency.

[D5:D3]Cmp_Ref2..0 [Data Comparator reference Level]

Set the tracking time constant τ under the following conditions.

- 1. No use of Data Comparator Quick Charge 1 & 2
- 2. Certain time has spent after starting Data Comparator Quick Charge 1.
- 3. An absolute value of the difference between vref and vi (Data comparator input voltage) will be less than the threshold level set by register:h'11[D7:D0]Charge2_Th7..0.

tracking time constant τ : $\tau = nr / fbc$

nr: Setting value of this register:[D5:D3]Cmp_Ref2..0 (Refer to the table below.)

fbc: Internal clock signal frequency depends on Bit Rate Filter register:h'0E [D4:D1]BRF_Bit3..0

[D5]Cmp_Ref2	[D4]Cmp_Ref1	[D3]Cmp_Ref0	1/nr	nr
0	0	0	1/128	128
0	0	1	1/256+1/512	170.7
0	1	0	1/256	256
0	1	1	1/512+1/1024	341.3
1	0	0	1/512	512
1	0	1	1/1024+1/2048	682.7
1	1	0	1/1024	1024
1	1	1	1/2048+1/4096	1365.3

See section 6.5.9 about Data Comparator Reference Voltage.

Notice: The cutoff frequency of Bit Rate Filter is derived from 30.32MHz Reference Clock Frequency.

[D2:D1] NIR_Frqth1..0 [NIR Filter Frequency Control]

[D1:D0] = b'00: 631 kHz (Initial Value)

[D1:D0] = b'01: 659 kHz [D1:D0] = b'10: 689 kHz [D1:D0] = b'11: 712 kHz

[D0] NIR_2L1

When to use NIR filter (h'10[D1]NIR_Fil_en = "1"), set this register "1".



6.10.20 h'1C Peak Hold Settings

Table 6-75 Register (h'1C)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	Peak_Ref2	Peak_Ref1	Peak_Ref0	Peak_ Charge1	Peak_ Charge0	NIR_2L0	NIR_L1	NIR_L0
Initial	1	0	0	0	1	0	0	0
Туре	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

[D7:D5] Peak_Ref2..0 [Limiter (Peak Hold Voltage Discharge Coefficient)]

When to set ASK Demodulation (h'0A[D4]FSK_ASK = "1") and Data Comparator Quick Charge 2 (h'10[D6]Charge2_en = "1"), this setting is valid. Set the discharge time constant of Peak Hold circuit.

Discharge time constant τ : $\tau = tr / fbc$

tr: Setting value of this register:Peak_Ref2..0 (Refer to the table below.)

fbc: Internal clock signal frequency depends on Bit Rate Filter register:h'0E [D4:D1]BRF_Bit3..0

[D7]Peak_Ref2	[D6]Peak_Ref1	[D5]Peak_Ref0	1/tr	tr
0	0	0	1/64	64
0	0	1	1/128+1/256	85.3
0	1	0	1/128	128
0	1	1	1/256+1/512	170.7
1	0	0	1/256	256
1	0	1	1/512+1/1024	341.3
1	1	0	1/512	512
1	1	1	1/1024+1/2048	682.7

See section 6.5.7 about Peak Hold circuit.

Notice: The cutoff frequency of Bit Rate Filter is derived from 30.32MHz Reference Clock Frequency.

[D4:D3] Peak_Charge1..0 [Limiter (Peak Hold Voltage Charge Coefficient)]

When to set ASK Demodulation (h'0A[D4]FSK_ASK = "1") and Data Comparator Quick Charge 2 (h'10[D6]Charge2_en = "1"), this setting is valid. Set the charging time constant peak tracking of Peak Hold circuit.

Charge time constant peak tracking τ : $\tau = tp' / fbc$

tp': Inverse of "(1/tp)+(1/tr)"

tp: Setting value of this register:Peak_Charge1..0 (Refer to the table below.)

tr: Setting value of this register:Peak_Ref2..0

fbc: Internal clock signal frequency depends on Bit Rate Filter register:h'0E [D4:D1]BRF_Bit3..0

[D4]Peak_ Charge1	[D3]Peak_ Charge0	1/tp	tp
0	0	1/8	8
0	1	1/16	16
1	0	1/32	32
1	1	1/64	64

See section 6.5.7 about Peak Hold circuit.

Notice: The cutoff frequency of Bit Rate Filter is derived from 30.32MHz Reference Clock Frequency.

[D2]NIR_2L0

When to use NIR filter (h'10[D1]NIR_Fil_en = "1") and Delay Detection (h'10[D0]Sel_Det = "0"), set this register "0". When to use NIR filter (h'10[D1]NIR_Fil_en = "1") and Pulse Count Detection (h'10[D0]Sel_Det = "1"), set this register "1".



[D1] NIR_L1

When to use NIR filter (h'10[D1]NIR_Fil_en = "1") and Delay Detection (h'10[D0]Sel_Det = "0"), set this register "1". When to use NIR filter (h'10[D1]NIR_Fil_en = "1") and Pulse Count Detection (h'10[D0]Sel_Det = "1"), set this register "0".

[D0]NIR_L0

When to use NIR filter (h'10[D1]NIR_Fil_en = "1"), set this register "0".

6.10.21 h'1D AutoOff Type B Setting

Table 6-76 Register (h'1D)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	Ontime7	Ontime6	Ontime5	Ontime4	Ontime3	Ontime2	Ontime1	Ontime0
Initial	0	0	0	0	0	0	0	0
Туре	R/W							

[D7:D0]Ontime7..0 [Duration]

When to set AutoOff Type B (h'10[D4]AutoOffB_en = "1"), this setting is valid.

Set value of timer period till the function of AutoOff Type B starts to operate. TC32306FTG will move to Battery Saving after the value of timer period is passed, if this IC will not find "Signal Detection" after the boot sequence.

- Setting Range

[D7:D0] = 0 - 255 (b'00000000 - b'11111111)

Initial Value: 0 (b'00000000) Maximum: 275.6ms(b'00000000) Minimum: 0ms(b'00000001)

- Way of setting

n: Setting value of register:[D7:D0]Ontime7..0

Setting value of timer period: $toff = 2^{15}/fosc \times (n-1)$ (except n = 0)

Setting value of timer period: $toff = 2^{15}/fosc \times 255$ (n = 0)

fosc: Reference Clock Frequency (30.32MHz)

Notice:

To be valid the setting of timer period, move TC32306FTG status from Battery Saving / Standby to Run after the register setting. The setting of timer period will be valid after the next moving from Battery Saving / Standby to Run, if the register setting will be described after the moving to Run. In EEPROM Mode, this register cannot be changed from the initial value.

6.10.22 h'1E Signal Detect and Lock Detect Monitors

Table 6-77 Register (h'1E)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	Lock_DET	DRSSI_DET	Noise_DET	Pre_DET	-	-	-	-
Туре	R	R	R	R	R	R	R	R

[D7]Lock_DET [Lock Detect Signal Monitor]

The status of PLL lock.

0: Unlocked

1: Locked

[D6]DRSSI_DET [RSSI Detection]

0: During the detection / Disable

1: Detected (RSSI_DET_out Signal = "H")

^{*} The Maximum & Minimum value of timer periods depend on 30.32MHz Reference Clock Frequency.



[D5]Noise_DET [Noise Detection]

0: During the detection / Disable

1: Detected (NDET_out Signal = "H")

[D4]Pre_DET [Preamble Detection]

0: During the detection / Disable

1: Detected (Preamble_DET_out Signal = "H")

[D3:D0]

This output is always "0".

6.10.23 h'1F Peak Hold Level Monitor

Table 6-78 Register (h'1F)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	PEAK7	PEAK6	PEAK5	PEAK4	PEAK3	PEAK2	PEAK1	PEAK0
Type	R	R	R	R	R	R	R	R

[D7:D0]PEAK7..0 [Peak Hold Level Monitor]

The output is 8 bit Peak Hold values of Peak Hold circuit. In FSK, the output this register is the value "b'000000000".

Notice:

In ASK, the register outputs the values of the Peak Hold Circuit without the function of Data Comparator Quick Charge 2.

6.10.24 h'20 Data Comparator Monitor 1

Table 6-79 Register (h'20)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	Ref_diff7	Ref_diff6	Ref_diff5	Ref_diff4	Ref_diff3	Ref_diff2	Ref_diff1	Ref_diff0
Туре	R	R	R	R	R	R	R	R

[D7:D0]Ref_diff7..0 [Data Comparator Reference Level Drift Monitor 1]

The output is 8 bit reference level drift of Data Comparator circuit. It is available to monitor for the adjustment for the register setting of that circuit. The output of 1 LSB will be equivalent to the drift of (1/1.53) kHz. The output this register is the value "b'11111111" when the drift increase than 165.75kHz. When the Digital Block circuits are disabled, the output of this register is the value "b'00000000".

6.10.25 h'21 Data Comparator Monitor 2

Table 6-80 Register (h'21)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	Ref_bias7	Ref_bias6	Ref_bias5	Ref_bias4	Ref_bias3	Ref_bias2	Ref_bias1	Ref_bias0
Туре	R	R	R	R	R	R	R	R

[D7:D0]Ref_bias7..0 [Data Comparator Average Reference Level Monitor]

The output is 8 bit average reference of the Data Comparator circuit. 1 LSB will be equivalent to the average of (1/1.53) kHz × 4 at the setting of FSK. When the Digital Block circuits are disabled, the output of this register is the value "b'00000000".



6.10.26 h'22 RSSI Level Monitor

Table 6-81 Register (h'22)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	DRSSI7	DRSSI6	DRSSI5	DRSSI4	DRSSI3	DRSSI2	DRSSI1	DRSSI0
Type	R	R	R	R	R	R	R	R

[D7:D0]DRSSI7..0 [Digital RSSI Level Monitor]

The output is 8 bit Digital RSSI level. When Digital RSSI circuit is disabled, the output of this register is the value "b'00000000".

6.10.27 h'23 Noise Signal Level Monitor

Table 6-82 Register (h'23)

	D7	D6	D5	D4	D3	D2	D1	D0
Name	DNDET7	DNDET6	DNDET5	DNDET4	DNDET3	DNDET2	DNDET1	DNDET0
Туре	R	R	R	R	R	R	R	R

[D7:D0]DNDET7..0 [Noise Detection Level Monitor]

The output is 8 bit Noise Detection level. When Noise Detection circuit is disabled, the output of this register is the value "b'00000000".

7. Absolute Maximum Ratings

Table 7-1 Absolute Maximum Ratings

(The temperature for unspecified temperature ranges is Ta = 25°C; voltage is ground referenced.)

Characteristics	Symbol / Pin Name	Rating	Unit
Power supply voltage 1	COM_VDD, A_VDD_5V	Min0.2 / Max. +6.0	V
Power supply voltage 2	A_VDD_3V	Min0.2 / Max. +3.6	V
Voltage difference between pins 1	COM_VDD - A_VDD_3V	Min0.2 / Max. +6.0	V
Voltage difference between pins 2	A_VDD_5V - A_VDD_3V	Min0.2 / Max. +6.0	V
Voltage difference between pins 3	COM_VDD - A_VDD_5V	Min0.2 / Max. +0.2	V
Input voltage (I/O pin)	DATA_IO, CS, CLK, MOSI, MISO	Min0.2 / Max. COM_VDD+0.2 or 6.0 (Whichever is lower.)	V
Input pin voltage 1	ENB, 3V/5V	Min0.2 / Max. COM_VDD+0.2 or 6.0 (Whichever is lower.)	V
Input pin voltage 2	RESET, TEST, MODE1, MODE2	Min0.2 / Max. +6.0	V
Input pin voltage 3	RX_SW, TX_SW	Min0.2 / Max. A_VDD_5V+0.2 or 6.0 (Whichever is lower.)	V
Signal pin voltage	RF_OUT, PA_OUT	Min0.2 / Max. +3.6	V
Maximum input power	RF_IN	Max. 10	dBm
Power dissipation	PD	Max. 1.0	W
Storage temperature range	Tstg	Min55 / Max. +125	°C

The absolute maximum ratings of a semiconductor device are a set of specified parameter values, which must not be exceeded during operation, even for an instant. If any of these rating would be exceeded during operation, the device electrical characteristics may be irreparably altered and the reliability and lifetime of the device can no longer be guaranteed. Moreover, these operations with exceeded ratings may cause break down, damage and/or degradation to any other equipment. Applications using the device should be designed such that absolute each maximum rating will never be exceeded in any operating conditions. Before using, creating and/or producing designs, refer to and comply with the precautions and conditions set forth in this documents.

8. Operating Range

Table 8-1 Operating Range

(The temperature for unspecified temperature ranges is Ta = 25°C; voltage is ground referenced.)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Temperature range	Topr	-	-	-40	25	110	°C
Supply voltage range (For 5V Use, in SPI Mode)	V _{DD (5V)}	-	-	2.4	5.0	5.5	V
Supply voltage range (For 3V Use, in SPI Mode)	V _{DD (3V)}	-	-	2.0	3.0	3.3	V
Supply voltage range (For 5V Use, in EEPROM Mode)	V _{DDE2P (5V)}	-	-	2.5	5.0	5.5	٧
Supply voltage range (For 3V Use, in EEPROM Mode)	V _{DDE2P (3V)}	-	-	2.5	3.0	3.3	٧
RF frequency range at 315MHz	f _{RF (315)}	-	IF = 230kHz/ Wide band XOSC: 30.32MHz	310	314.94	316	MHz
RF frequency range at 434MHz	f _{RF (434)}	-	IF = 230kHz/ Wide band XOSC: 30.32MHz	433	433.92	435	MHz
RF frequency range at 868MHz	f _{RF (868)}	-	IF = 230kHz/ Wide band XOSC: 30.32MHz	868	868	870	MHz
RF frequency range at 915MHz	f _{RF (915)}	-	IF = 230kHz/ Wide band XOSC: 30.32MHz	902	915	928	MHz
X_IN Signal input level	V_{X_IN}	-	Peak to peak value	0.5	-	1.5	V

The operating range indicates the conditions under which basic functional operation is possible even when there are fluctuations in the electrical characteristics of a device.

9. Electrical Data

(Unless otherwise specified, Ta = 25°C, V_{DD} = 5.0V (For 5V use), fin(RF) = 314.94MHz, fin(X_IN) = 30.32MHz, Vin(X_IN) = 1.5Vp-p, deviation = +/-40kHz, fmod = 600Hz, FSK modulation, ENB = High, f(IF) = 230kHz(Wide band), Set register:h'0A[D7] = "1", Set other registers initial)

Table 9-1 General Characteristics

Characteristics	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Current consumption, RF-receiving, no signal, FSK 1	I _{DDfm (RX)1}	11-2	314.94MHz	7.2	9.7	12.2	mA
Current consumption, RF-receiving, no signal, FSK 2	I _{DDfm (RX)2}	11-2	433.92MHz	6.9	9.2	11.5	mA
Current consumption , RF-receiving, no signal, FSK 3	I _{DDfm (RX)3}	11-2	868MHz, 915MHz	8.1	10.8	13.5	mA
Current consumption , RF-receiving, no signal, ASK 1	I _{DDam (RX)1}	11-2	314.94MHz	7.4	9.9	12.4	mA
Current consumption , RF-receiving, no signal, ASK 2	I _{DDam (RX)2}	11-2	433.92MHz	7.1	9.5	11.9	mA
Current consumption , RF-receiving, no signal, ASK 3	I _{DDam (RX)3}	11-2	868MHz, 915MHz	8.3	11.1	13.9	mA
Current consumption , RF-transmitting 1	I _{DD (TX)1}	11-2	314.94MHz, TX, Set maximum output, Unmodulated	9.0	12.0	15.0	mA
Current consumption , RF-transmitting, PA off	I _{DD (TX)PAOFF}	11-2	314.94MHz, TX, PA off, Unmodulated	3.6	4.8	6.0	mA
Current consumption, in Battery Saving	I _{DD (BS)}	11-2	-	-	0	5	μА

Table 9-2 Pin Characteristics

Characteristics	Symbol	Test Circuit	Tes	st Condition		Min	Тур.	Max	Unit
Input low voltage 1	V _{IL1}	-				-0.2	0	COM_VDD × 0.2	V
Leakage current 1 (Low voltage input)	I _{IL1}	-	ENB, RESI	ET, 3V/5V, MO	DE2,	-	-	5	μА
Input high voltage 1	V _{IH1}	-	DATA_IO, M	ISO, MOSI, CI	_K, CS	COM_VDD × 0.8	COM_VDD	COM_VDD +0.2	V
Leakage current 1 (High voltage input)	I _{IH1}	-				-	-	5	μА
Input low voltage 2	Input low voltage 2 V _{IL2} -					-0.2	0	A_VDD_5V × 0.2	V
Leakage current 2 (Low voltage input)	I _{IL2}	-	DV	CM TV CM		-	-	5	μА
Input high voltage 2	V _{IH2}	-	KA_	SW, TX_SW		A_VDD_5V × 0.8	A_VDD_5V	A_VDD_5V +0.2	V
Leakage current 2 (High voltage input)	I _{IH2}	-				-	-	5	μА
Output resistance	R _{OH1}	-		Low Drive		7.5	10	12.5	kΩ
Output low voltage 1	V _{OL1}	-	DATA_IO, DET_TMONI1,	High Drive	I _{OL} = 0.5mA	-	-	0.4	V
Output high voltage 1	V _{OH1}	-	DET_TMONI2	Tilgii Diive	I _{OH} = -0.5mA	4.6	-	-	٧
Output low voltage 2	V _{OL2}	-		Low Drive	I _{OL} = 0.5mA	-	-	0.4	٧
Output high voltage 2	V _{OH2}	-	MISO	Low Drive	I _{OH} = -0.5mA	4.6	-	-	V
Output low voltage 3	V _{OL3}	-	MISO	High Daire	I _{OL} = 1.0mA	-	-	0.4	V
Output high voltage 3	V _{OH3}	-		High Drive	I _{OH} = -1.0mA	4.6	-	-	V
Output low voltage 4	V_{OL4}	-	CLK CC	MOSI	I _{OL} = 1.0mA	-	-	0.4	V
Output high voltage 4	V _{OH4}	-	CLK, CS, MOSI		I _{OH} = -1.0mA	4.6	-	-	V
Output high voltage 5	V _{OH5}	-	RX_SW,	TX_SW	I _{OH} = -2.0mA	4.2	-	-	V

Table 9-3 RF-Receiving Characteristics

Characteristics	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
LNA gain	G _{v (LNA)}	11-4	50 Ω termination	-11	-8	-5	dB
IF filter lower cutoff frequency 1	IF _{L1}	1	fo-3dB point IF = 230kHz / Wide band	-	70	90	kHz
IF filter higher cutoff frequency 1	IF _{H1}	i	fo-3dB point IF = 230kHz / Wide band	370	390	-	kHz
IF filter lower cutoff frequency 2	IF _{L2}	1	fo-3dB point IF = 280kHz / Middle band	-	140	160	kHz
IF filter higher cutoff frequency 2	IF _{H2}	-	fo-3dB point IF = 280kHz / Middle band	390	410	-	kHz
RSSI output voltage 1	V _{RSSI1}	11-5	V _{IN (MIX)} = -80dBm, Unmodulated	0.30	0.55	0.80	V
RSSI output voltage 2	V_{RSSI2}	11-5	$V_{IN (MIX)} = -60 dBm,$ Unmodulated	0.85	1.25	1.60	V
RSSI output voltage 3	V _{RSSI3}	11-5	V _{IN (MIX)} = -30dBm, Unmodulated	1.85	2.35	2.80	V
RSSI output resistance	R _{RSSI}	11-3	-	37.5	50	62.5	kΩ
Duty ratio	DR_{fm}	11-5	V _{IN (MIX)} = -60dBm, DATA_IO pin output, Data pattern: 010101···	45	50	55	%

(Unless otherwise specified, Ta = 25°C, V_{DD} = 5.0V (For 5V use), fin(RF) = 314.94MHz, fin(X_IN) = 30.32MHz, Vin(X_IN) = 1.5Vp-p, FSK modulation, ENB = High, RF transmitting, Unmodulated, Set register:h'0A[D7] = "1", Set other registers initial)

Table 9-4 RF-Transmitting Characteristics

Characteristics	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Output level (315MHz) 1	P _{TX (315)1}	11-6	FSK, 314.94MHz,Unmodulated, Via a matching circuit, Set maximum output,	8	10	12	dBm
			ASK, 314.94MHz, Peak power, Via a matching circuit, Set maximum output,				

10. Reference Characteristics Data

This item contains reference values and does not contain any guaranteed values.

(Unless otherwise specified, Ta = 25°C, VDD = 5.0V (For 5V use), fin(RF) = 314.94MHz, $fin(X_IN) = 30.32MHz$, $Vin(X_IN) = 1.5Vp$ -p, deviation = +/-40kHz, finod = 600Hz, FSK modulation, ENB = High, f(IF) = 230kHz(Wide band), Set register: h'0A[D7] = "1", Set other registers initial)

Table 10-1 Reference General Characteristics Data

Characteristics	Symbol	Test Circuit	Test Condition	Тур.	Unit
Regulator output voltage 1	A_REG30	-	For 5V use	3.0	V
Regulator output voltage 2	A_REG15	-	-	1.5	V
Regulator output voltage 3	D_REG	-	-	1.5	V
Regulator output voltage 4	PLL_REG	-	-	1.5	V

Table 10-2 Reference RF-Receiving Characteristics Data

Characteristics	Symbol	Test Circuit	Test Condition	Тур.	Unit
Receiver sensitivity 12dB SINAD1	12dB SINAD1	-	314.94/ 433.92MHz, IF = 280kHz / Middle band, FSK, Deviation = +/-40kHz	-117	dBm
Receiver sensitivity 12dB SINAD2	12dB SINAD2	-	314.94/ 433.92MHz, IF = 230kHz / Wide band, FSK, Deviation = +/-40kHz	-116	dBm
Receiver sensitivity 12dB SINAD3	12dB SINAD3	-	915MHz, IF = 280kHz / Middle band, FSK, Deviation = +/-40kHz, except for the harmonics of reference clock	-116	dBm
Receiver sensitivity 12dB SINAD4	12dB SINAD4	-	915MHz, IF = 230kHz / Wide band, FSK, Deviation = +/-40kHz, except for the harmonics of reference clock	-115	dBm
Receiver sensitivity 12dB SINAD5	12dB SINAD5	=	314.94 MHz, IF = 230kHz / Wide band, ASK, 90% depth, square wave input	-121	dBm
LNA voltage gain (315 / 434 MHz)	G _{v (LNA)H}	-	314.94 / 433.92MHz, via a matching circuit	35	dB
LNA voltage gain (868 / 915 MHz)	G _{v (LNA)L}	-	868 / 915MHz, via a matching network	26	dB
Mixer conversion gain 1	G _{v (MIX)1}	-	314.94 / 433.92MHz, 50 Ω termination	31	dB
Mixer conversion gain 2	G _{v (MIX)2}	-	868 / 915MHz, 50 Ω termination	35	dB
Mixer Intercept point (3rd order)	IIP3	-	Input referred value	-9	dBm
Mixer 1dB compression	IP1dB	-	Input referred value	-18	dBm
Image rejection ratio	IRR	-	-	35	dB
IF AMP gain	G _{v (IF)}	-	-	51	dB
IF filter attenuation	IFF _{ATT}	-	300kHz offset, IF = 280kHz / Middle band	18.6	dB

(Unless otherwise specified, Ta = 25°C, V_{DD} = 5.0V (For 5V use), fin(RF) = 314.94MHz, fin(X_IN) = 30.32MHz, V_{DD} = 1.5Vp-p, FSK modulation, ENB = High, RF transmitting, Unmodulated, Set register:h'0A[D7] = "1", Set other registers initial)

Table 10-3 Reference RF-Transmitting Characteristics Data

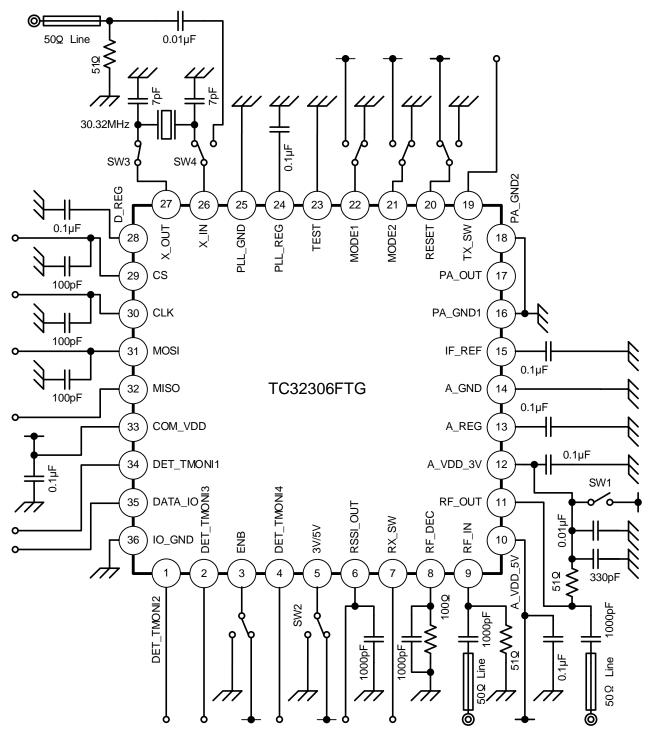
Characteristics	Symbol	Test Circuit	Test Condition	Тур.	Unit
Current consumption , RF-transmitting 2	I _{DD (TX)2}	-	Register:h'13 [D3:D2] = "10"	10.4	mA
Current consumption , RF-transmitting 3	I _{DD (TX)3}	-	Register:h'13 [D3:D2] = "01"	8.8	mA
Current consumption , RF-transmitting 4	I _{DD (TX)4}	-	Register:h'13 [D3:D2] = "00" (Minimum level)	7.3	mA
RF-transmitting power level (315MHz) 2	P _{TX (315)2}	-	Register:h'13 [D3:D2] = "10"	8	dBm
RF-transmitting power level (315MHz) 3	P _{TX (315)3}	-	Register:h'13 [D3:D2] = "01"	4.7	dBm
RF-transmitting power level (315MHz) 4	P _{TX (315)4}	-	Register:h'13 [D3:D2] = "00" (Minimum level)	0	dBm

Table 10-4 Reference PLL Characteristics Data

Characteristics	Symbol	Test Circuit	Test Condition	Тур.	Unit
Lockup time	T _{PLL}	-	-	50	μS
450kHz offset C/N (RF-transmitting)	C/N1	-	315 / 434MHz, Unmodulated	70	dBc/ 100kHz
1MHz offset C/N (RF-transmitting)	C/N2	-	915MHz, Unmodulated	60	dBc/ 300kHz

11. Typical Test Circuit

The components illustrated in the test circuit diagrams that follow are only used to confirm device characteristics. To shiba does not guarantee that these components will prevent malfunction or failure in your particular application device.

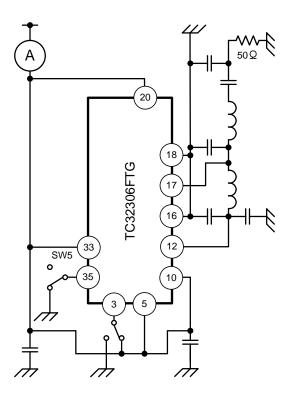


Test Characteristics: $V_{DD\,(5V)}$, $V_{DD\,(3V)}$, $f_{RF\,(315)}$, $f_{RF\,(434)}$, $f_{RF\,(868)}$, $f_{RF\,(915)}$

Notice

Measure after the parts tuning that shows a part number. TC32306FTG supply voltage is selected by SW1 and SW2. SW3 and SW4 allow selecting the crystal oscillator and external signal.

Fig 11-1 Typical Test Circuit



 $\begin{array}{l} \textbf{Test Characteristics: } I_{\text{DDfm}} \ (\text{RX})1, \ I_{\text{DDfm}} \ (\text{RX})2, \ I_{\text{DDfm}} \ (\text{RX})3, \ I_{\text{DDam}} \ (\text{RX})1} \\ I_{\text{DDam}} \ (\text{RX})2, \ I_{\text{DDam}} \ (\text{RX})3, \ I_{\text{DD}} \ (\text{TX})1, \ I_{\text{DD}} \ (\text{TX})\text{PAOFF}, \ I_{\text{DD}} \ (\text{BS})} \end{array}$

* For 5V mode, set 5 pin to high level.

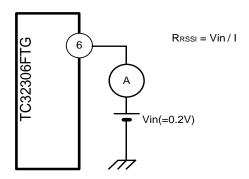
In the measurement of RF-Receiving, set to be open 35 pin by operating SW5.

In the measurement of RF-Transmitting, set to be low level and set to unmodulated by register. In the measurement of RF-Transmitting without PA operation, set the register:h13[D1]PA_en = "0".

Also in the measurement of RF-Transmitting, set the output pin via a 50Ω termination as illustrated.

In the measurement of Battery Saving Status, set 3 pin to low level.

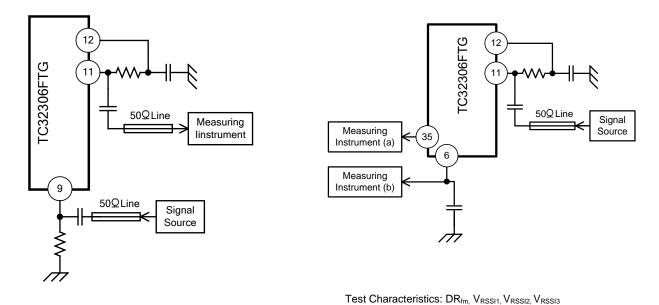
Fig 11-2 Test Circuit (Current Consumption)



Test Characteristics: R_{RSSI}

* It will be measured at no voltage supply to TC32306FTG, and applied lower voltage not to work internal protection diodes.

Fig 11-3 Test Circuit (RSSI_OUT Pin Output Resistance)



Test Characteristics: G_{v (LNA)}

Fig 11-4 Test Circuit (LNA Gain)

* Measure DRfm by connecting (a).

Measure $V_{\text{RSSI1}}\!/V_{\text{RSSI2}}\!/V_{\text{RSSI3}}$ by connecting (b).

Fig 11-5 Test Circuit (RF-Receiving)

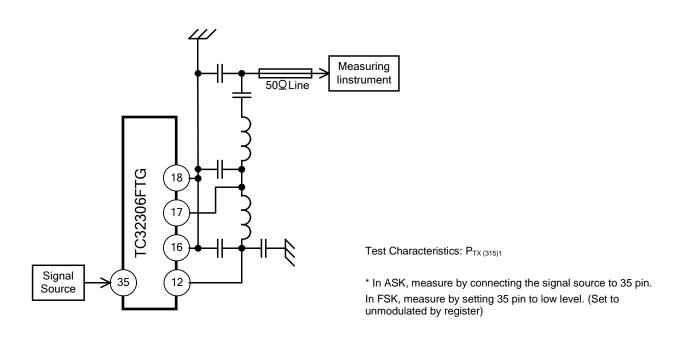
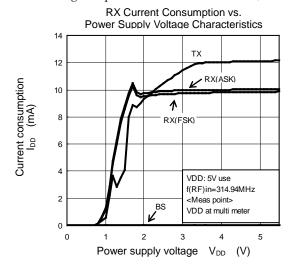
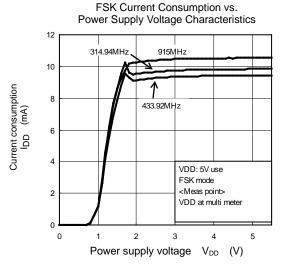


Fig 11-6 Test Circuit (RF-Transmitting)

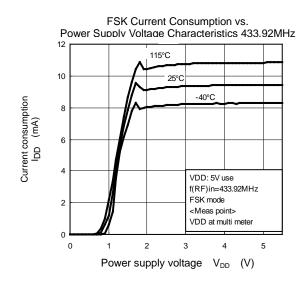
12. Reference data

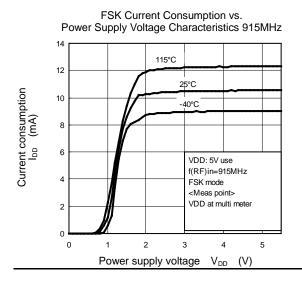
(This is temperature characteristics data when it used test circuit boards. This is not guarantee on condition that it is stating except electrical characteristics.)

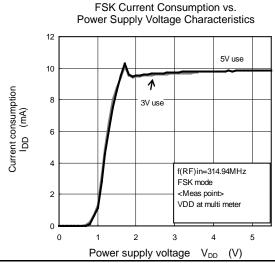




FSK Current Consumption vs. Power Supply Voltage Characteristics 314.94MHz 115°C 25°C 10 Current consumption Ipp (mA) -40°C VDD: 5V use f(RF)in=314.94MHz FSK mode 2 <Meas point> VDD at multi mete 0 0 2 5 Power supply voltage V_{DD} (V)



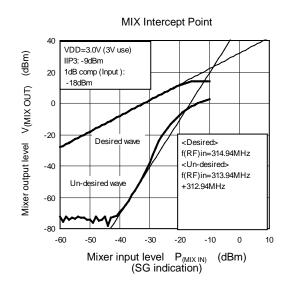




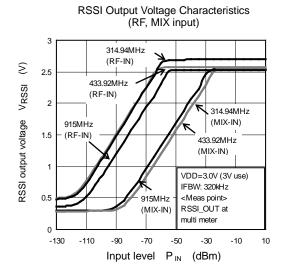
Power Supply Voltage Characteristics 314.94MHz 115°C 12 10 -40°C

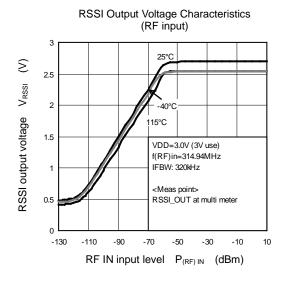
ASK Current Consumption vs.

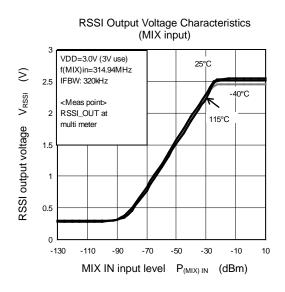
Current consumption lop (mA) VDD: 5V use f(RF)in=314.94MHz ASK mode <Meas point> VDD at multi meter 0 5 Power supply voltage V_{DD} (V)

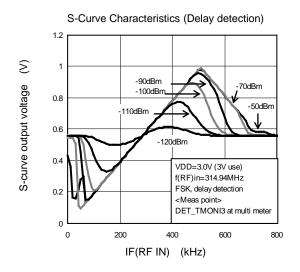


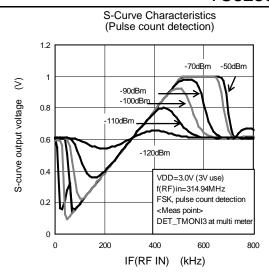
IF Filter Characteristics 10 Wide band 0 -10 Mjddle ban -20 -30 -40 -50 -60 -70 VDD=3.0V (3V use) f(MIX)in=314.94MHz -80 -90 $IF_{(\mathsf{RF}\;\mathsf{IN})}$ (kHz)

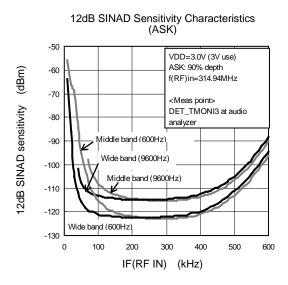


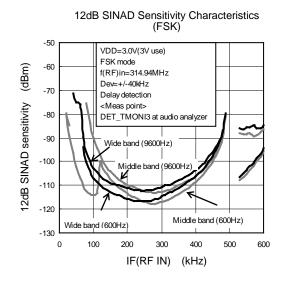


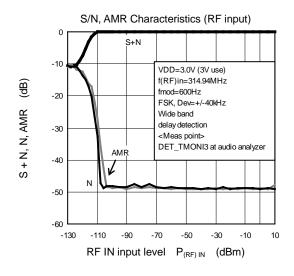


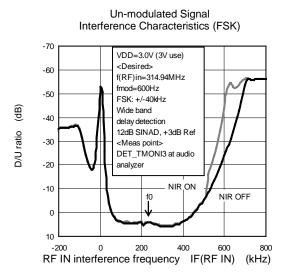












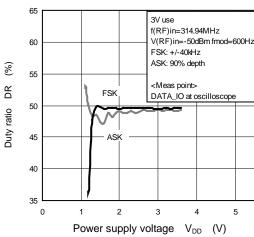
88

35

0

Duty Ratio vs. Power Supply Voltage Characteristics (5V use) 60 55 % FSK Я 50 5V use Duty ratio ASK f(RF)in=314.94MHz 45 V(RF)in=-50dBm fmod=600Hz FSK: +/-40kHz ASK: 90% depth 40

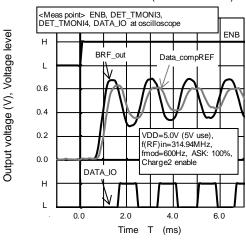
Duty Ratio vs. Power Supply Voltage Characteristics (3V use)



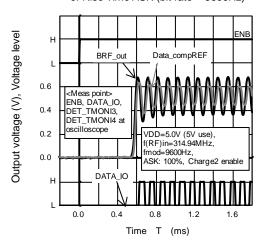
Data Comparator, Response Characteristics of Rise Time ASK (bit rate = 600Hz)

Power supply voltage V_{DD} (V)

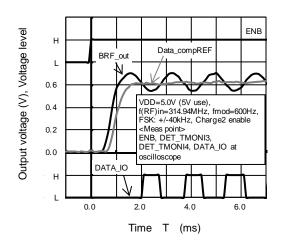
<Meas point>
DATA_IO at oscilloscope



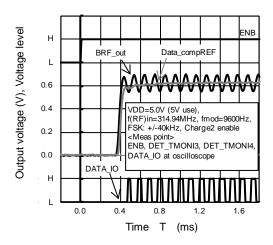
Data Comparator, Response Characteristics of Rise Time ASK (bit rate = 9600Hz)

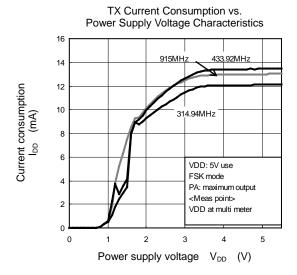


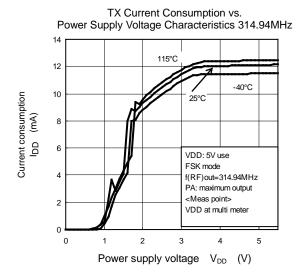
Data comparator, Response Characteristics of Rise Time FSK (bit rate = 600Hz)

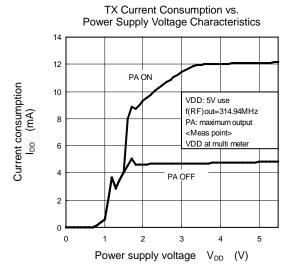


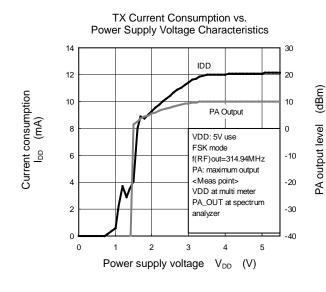
Data comparator, Response Characteristics of Rise Time FSK (bit rate = 9600Hz)

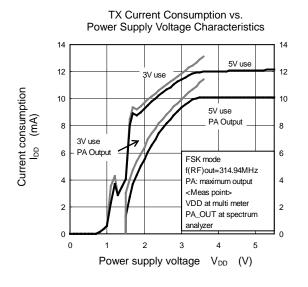






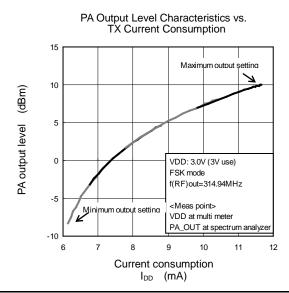


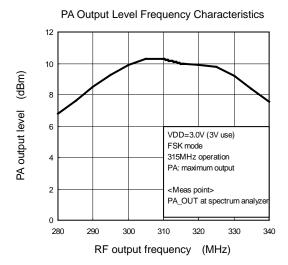




(dBm)

PA output level





13. Application Circuits

To shib a does not guarantee this application circuit example as a production design. Please evaluate carefully when developing the production design for your application.

13.1 Example of Evaluation Circuit

Fig 13-1 is an example of Toshiba's evaluation circuit.

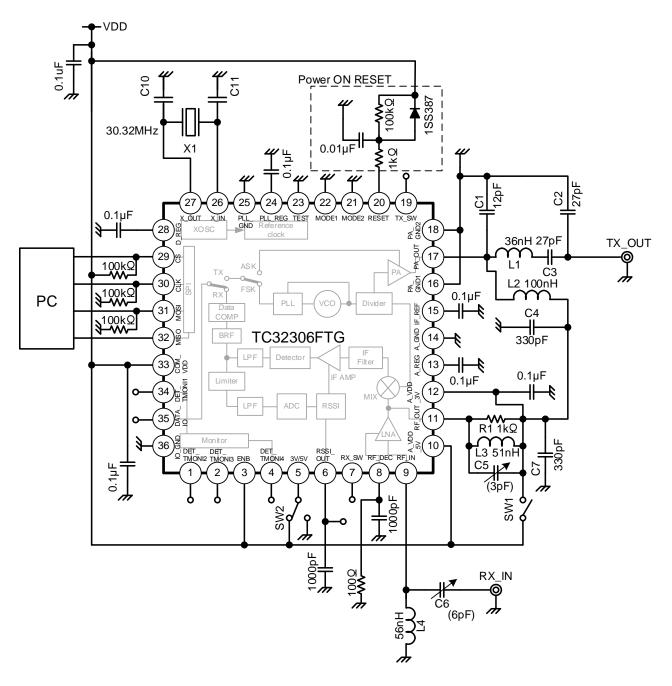


Fig 13-1 Example of Evaluation Circuit

TOSHIBA TC32306FTG

- Above circuit is a 5V use. For 3V use, connect SW2 to low level, and be short circuit in SW1.
- Above circuit is a use for 315MHz and the circuit parts constants are suitable for that frequency. For other frequency use, see Table 13-1.
- Above circuit is SPI Mode and external PC controls to read or write register of TC32306FTG,
- In above circuit, a control of an antenna switch is not use.
- The capacitor C5 and C6 is adjusted by a trimmer capacitor.

Toshiba use capacitors shown in the following, Murata Manufacturing Company, Ltd.

i. TZY2Z060A001 (6pF)

ii.TZY2Z030A001 (3pF)

iii. TZY2Z010A001 (1pF)

- The inductance L1-L4: LQW18 series, Murata Manufacturing Company, Ltd.

- X1:

FCX-04 30.320MHZ-J90842, RIVER ELETEC CORPORATION C10 =9pF / C11 = 9pF

Or

NX3225SC EXS00A-CS03981 (30.320MHz), NIHON DEMPA KOGYO CO., LTD. C10 = 9pF/C11 = 9pF

Or

CX3225SA30320B0GPQCC, KYOCERA Crystal Device Corporation C10 =10pF / C11 = 9pF

Table 13-1 Example of Matching Constants

Frequency	315MHz	434MHz	915MHz
C1	12pF	10pF	4pF
C2	27pF	20pF	9pF
C3	27pF	18pF	6pF
C4	330pF	330pF	330pF
C5	ii *	ii *	iii *
C6	i *	i *	1pF
C7	330pF	330pF	330pF
L1	36nH	22nH	10nH
L2	100nH	100nH	43nH
L3	51nH	22nH	6.8nH
L4	56nH	33nH	9.1nH
R1	1kΩ	2kΩ	510Ω

*: usage trimmer capacitor

13.2 Example of Application Circuit 1

Fig 13-2 is an example of application circuit controlled by MCU. (Bidirectional communication / 3V Use)

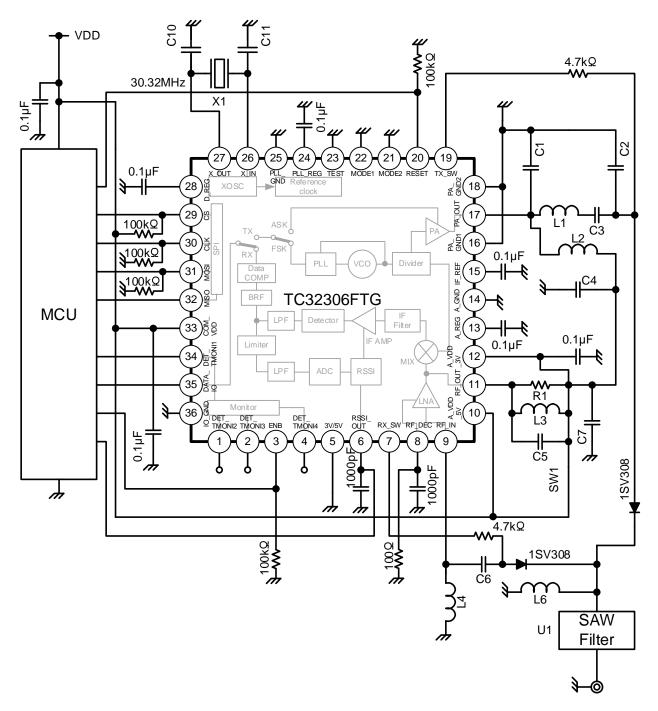


Fig 13-2 Example of Application Circuit 1

94

- Fig 13-2 is SPI Mode and external MCU I/O is connected to SPI control pins of TC32306FTG,
- Fig 13-2 is 3V Use. For 5V Use, change the voltage supply connections by referring Fig 13-1.
- Do not connect DC voltage except ground to RF_IN pin.
- MCU also controls RESET pin and ENB pin.
- MCU accepts a signal from DET_TMONI1 pin as an interrupt signal.
- MCU monitors RSSI_OUT pin signal.
- The antenna is use for RX and TX, and this IC controls the antenna switch, 1SV308: Toshiba Corporation.
- About resistors, capacitors and coils values in the circuit, consider referring to the evaluation circuit of section 13.1.

13.3 Example of Application Circuit 2

Fig 13-3 is an example of application circuit controlled by MCU. (For receiving only / 3V Use)

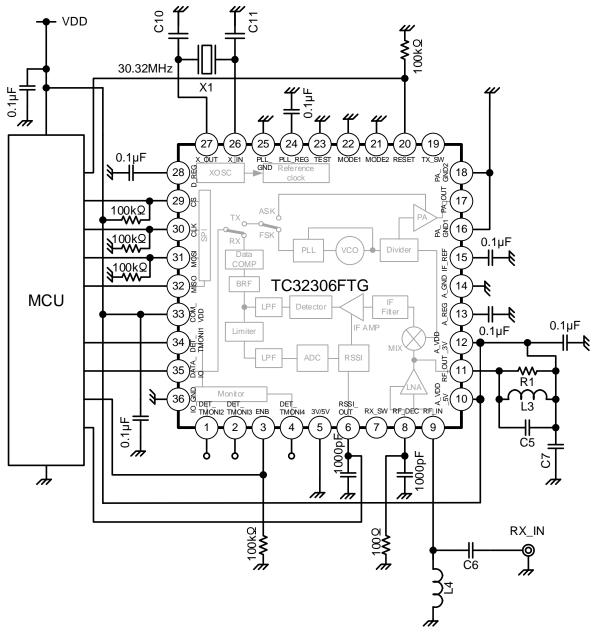


Fig 13-3 Example of Application Circuit 2

95

- Fig 13-3 is SPI Mode and external MCU I/O is connected to SPI control pins of TC32306FTG,
- Fig 13-3 is 3V Use. For 5V Use, change the voltage supply connections by referring Fig 13-1.
- Do not connect DC voltage except ground to RF_IN pin.
- PA_OUT pin is open.
- MCU also controls RESET pin and ENB pin.
- MCU accepts a signal from DET_TMONI1 pin as an interrupt signal.
- MCU monitors RSSI_OUT pin signal.
- About resistors, capacitors and coils values in the circuit, consider referring to the evaluation circuit of section 13.1.

13.4 Example of Application Circuit 3

Fig 13-4 is an example of application circuit controlled by MCU and EEPROM. (Bidirectional communication / 5V Use)

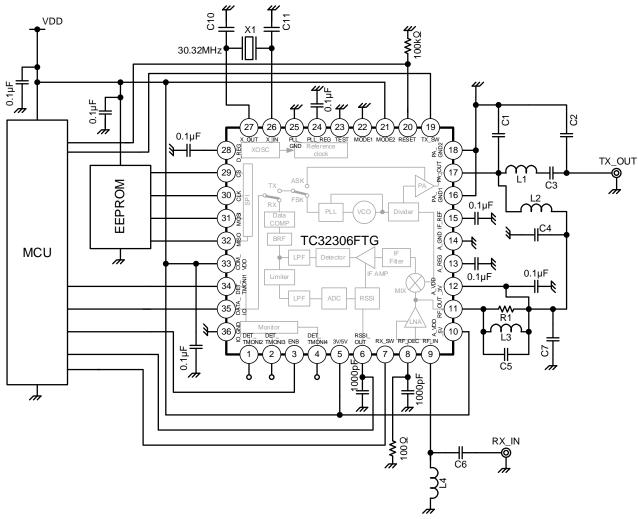


Fig 13-4 Example of Application Circuit 3

- Fig 13-4 is EEPROM Mode and external EEPROM I/O is connected to SPI control pins of TC32306FTG,
- Fig 13-4 is 5V Use. For 3V Use, change the voltage supply connections by referring Fig 13-1.
- Do not connect DC voltage except ground to RF_IN pin.
- MCU controls RESET pin.
- MCU controls ENB pin, RX_SW pin and TX_SW pin to set configuration of EEPROM.
- MCU accepts a signal from DET_TMONI1 pin as an interrupt signal.
- MCU monitors RSSI_OUT pin signal.
- In EEPROM Mode, this IC doesn't prepare antenna switch control.
- About EEPROM pin termination, see that manual.

(for example: SPI Serial EEPROM S-25A010A/020A/040A series, Seiko Instruments Inc.)

- About resistors, capacitors and coils values in the circuit, consider referring to the evaluation circuit of section 13.1.

13.5 Example of Application Circuit 4

Fig 13-5 is an example of application circuit only for receiving controlled by MCU and EEPROM. (For receiving only / 5V Use)

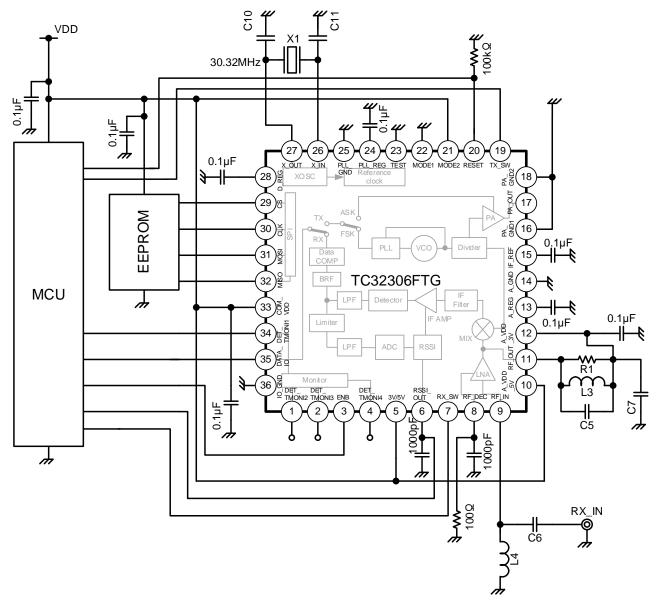
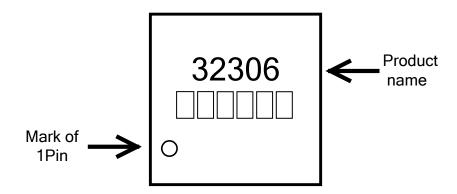


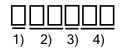
Fig 13-5 Example of Application Circuit 4

- Fig 13-5 is the EEPROM Mode and external EEPROM I/O is connected to SPI control pins of TC32306FTG,
- Fig 13-5 is 5V Use. For 3V Use, change the voltage supply connections by referring Fig 13-1.
- Do not connect DC voltage except ground to RF_IN pin.
- PA_OUT pin is open.
- MCU controls RESET pin.
- MCU controls ENB pin, RX_SW pin and TX_SW pin to set configuration of EEPROM.
- MCU accepts a signal from DET_TMONI1 pin as an interrupt signal.
- MCU monitors RSSI_OUT pin signal.
- In EEPROM Mode, this IC doesn't prepare antenna switch control.
- About EEPROM pin termination, see that manual.
- About resistors, capacitors and coils values in the circuit, consider referring to the evaluation circuit of section 13.1.

14. Marking (Top View)

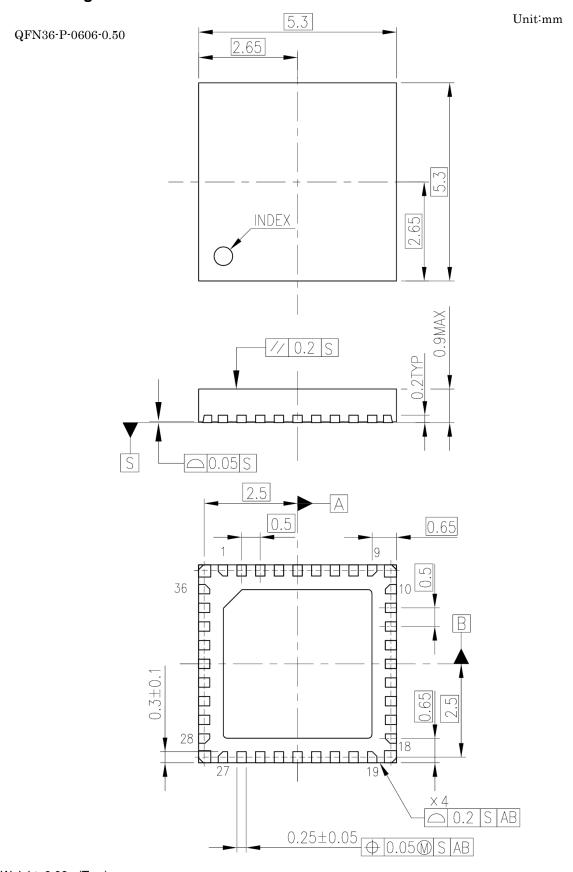


Lot Code



- 1) The year of manufacture (1 last figure of the year)
- 2) The week of manufacture ("01" as first week of the year, from 1 to 52 or 53)
- 3) Toshiba factory management code
- 4) Assembly code

15. Package Dimensions



Weight: 0.08g (Typ.)

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